

# **VLSI Physical Design**

**Offline Internship Report**

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***Report Submitted by***

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*In partial fulfilment for the award if the degree of*

**Bachelor of Engineering**

*in*

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Dr. S. & S.S. Ghandhy Government Engineering College, Surat



**Gujarat Technological University, Ahmedabad**

**June-July 2024**



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### Certificate

Date:

This is to certify that the project report submitted along with the project entitled **VLSI Physical Design** has been carried out by **Sahu Arabinda Kailash** under my guidance in partial fulfilment for the degree of Bachelor of Engineering in Electronics and Communication Engineering, 7th Semester of Gujarat Technological University, Ahmedabad during the academic year 2024-25.

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## DECLARATION OF ORIGINALITY

I hereby declare that the Internship report submitted along with the Internship entitled VLSI Physical design submitted in partial fulfilment for the degree of Bachelor of Engineering in Electronics and Communication engineering to Gujarat Technological University, Ahmedabad, is a bonafide record of original project work carried out by me at SVNIT under supervision of Dr. Pinalkumar J. Engineer and that no part of this report has been directly copied from any students reports or taken from any other source, without providing due reference.

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## ACKNOWLEDGMENT

This is the place to admit that while there appears only author on the cover, this work just as any other, is a product of the interaction with and support during our internship work, among them, first I express my gratitude to my guides Dr. Pinalkumar J. Engineer & Prof. Dharmesh J. Patel for their affection throughout guidance, advice, and encouragement. Special thanks to my college for giving me the invaluable knowledge. Also, I interacted with some other students having their study and research there for guidance of software installation, I am grateful to them also for providing us guidance. Above all I am thankful to almighty God for everything.

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## LIST OF ABBREVIATIONS

<b>Symbol</b>	<b>Abbreviations</b>
SVNIT	Sardar Vallabhbhai National Institute of Technology
RTL	Register Transfer Level
GDS	Graphic Design System
IC	Integrated Circuit
VLSI	Very Large-Scale Integration
RCA	Ripple Carry Adder
CSA	Carry Save Adder
CLA	Carry Look Ahead Adder
E.C.	Electronics and Communication
nm	nano meter
FET	Field Effect Transistor
TSMC	Taiwan Semiconductor Manufacturing Company
GAA	Gate-All-Around
AI	Artificial Intelligence
ASIC	Application Specific Integrated Circuit
SoC	System-on-Chip
EDA	Electronic Design Automation
GTU	Gujarat Technological University
DGGEC	Dr. S. & S.S. Ghandhy Government Engineering College
ALU	Arithmetic Logic Unit
VHDL	Very High-Speed Integrated Circuit Hardware Description Language
LSB	Least Significant Bit
MSB	Most Significant Bit
DSP	Digital Signal Processing
EDA	Electronic Design Automation
CAD	Computer-aided Design
ORFS	OpenROAD-flow-scripts
SDC	Synopsys Design Complier

GUI	Graphic User Interface
HDL	Hardware Description Language
WSL	Windows Subsystem Linux
VMBox	Virtual Machine Box
PDK	Process Design Kit
CTS	Clock Tree Synthesis
BLIF	Berkely Logic Interchange Format
PDN	Power Distribution Network
SDC	Synopsys Design Constraints
SPEF	Standard Parasitic Exchange Format
um	micro meter

## ABSTRACT

The main objective of the internship program is to learn about the RTL to GDS Design flow of Digital circuits to form an IC. In the journey of this learning, we learned about advanced adders and multipliers and some other components. Also, during the program, we learned about opensource tools and software related to ASIC designing process. The SVNIT has great environment and guidance for learnings. The internship is focused to the vlsi physical design flow in digital field. In duration of these internship, I learned a lot about Physical design aspect of VLSI and looking forward for VLSI ASIC design related works and projects.

## CHAPTER 1: INTRODUCTION

In the E.C Engineering various Electronics devices are used such as resistor, transistors, diodes, and ICs. Among those devices IC are game changer technology. And all this possible due to semiconductors. Such as Silicon, graphene, etc. are generally used to form IC.

The current IC technology window reached is of 5-3nm only. Further research to narrow the channel length of FETs is going on. The SoC such as Tensor G3 used in Google Pixel 8 Series, M3 used in latest MacBook, Exynos 2400 in galaxy S24 series, Qualcomm's Snapdragon S gen 3 in Samsung galaxy S24 ultra are one of the latest technology-based ASICs designed by foundries such as TSMC, GAA, and Samsung. Recently Nvidia become first company to research on IC based AI neural engines and render engines. All this discussion to ensure that our internship program for VLSI physical design flow is to learn about designing of ASICs.

In most of Indian ASIC based companies are service based such as designing or testing and verification is carried out. I chose this topic of internship to explore about ASIC and RTL-to-GDS design flow.

### 1.1 INTERNSHIP DESCRIPTION

The Summer Internship of 2 weeks is a part of GTU academics extra curriculum activity allowing students to get hands on experience before placement drives in campus. This report outlines the experiences and accomplishments during the internship period at the VLSI Research Lab in Electronics Engineering Department of SVNIT, under the mentorship and supervision of Dr. Pinalkumar J. Engineer, Associate Professor at SVNIT. Duration of internship as mentioned by GTU Notification 29<sup>th</sup> June 2024 to 12<sup>th</sup> July 2024. During this period in 11 working days, the internship focused on the VLSI physical design flow in digital domain, providing exposure in implementing various digital circuits as RTL-to-GDS design such as RCA, CLA, CSA, Array Multipliers etc. VLSI technology is pivotal in the enhancement or advancement of modern electronics, enabling the creation of complex IC by combining thousands or millions of transistors onto a single chip. The

physical design phase in VLSI involves conversion of a high-level abstract design into a detailed manufacturable layout. This phase is crucial as it directly impacts the performance, power consumption, heat dissipation, and overall efficiency of IC.

## 1.2 SCOPE AND OBJECTIVE OF INTERNSHIP

### 1.2.1 Objectives

The primary objectives of internship were:

- To gain practical knowledge of the VLSI physical design flow.
- To implement and optimize physical designs for different types of digital circuits.
- To understand the tools and methodologies used in the VLSI design flow.

### 1.2.2 Scope of internship

During the internship the below mentioned tasks were undertaken:

- Implementation of different advanced adders and multiplier circuits in Xilinx tool for RTL and Simulation.
- Designing and Optimization of various integrated circuits.
- Use of opensource EDA tools for layout design, verification, and optimization.

This internship provided valuable insights into the intricacies of VLSI physical design, bridging the gap between theoretical knowledge and practical application. The experience gained has equipped me with the skills and understanding necessary to contribute effectively to the field of VLSI design.

## CHAPTER 2: DESIGN ON XILINX

The initial stage of VLSI physical design flow is implementing the design module and verify the simulation output. For this we can create files such as Verilog file with “.v” extension, VHDL modules with “.vhdl” file extension and “.tb” file extension for test bench. Those files are used to form the RTL, Schematics and Verification by simulation of logics with test vectors at Test bench. Apart from general digital circuits we learned in VLSI design subject and DSD subject of GTU syllabus I learned about multipliers and Advanced 8 bit and extensible digital circuit designs.

### 2.1 ADVANCED ADDER DESIGNS

In advanced adder architecture i learned about 3 kinds of adders used in forming ALUs and intermediate stage of multipliers used in ALU. The 3 kinds of Adder design I learned are 1) Ripple Carry Adder, 2) Carry Save Adder, 3) Carry Look Ahead Adder. Those adders have their specific application and use cases based on their design parameters such as size, delay, performance for n bits architecture and area occupied on chip etc. I have designed and implemented as per given instructions using VHDL programming and of 8 bits architecture for all these kinds. Let’s see more about different adder designs in further sections.

#### 2.1.1 Ripple Carry Adder (RCA)

A Ripple Carry Adder is digital binary adder circuit designed to two n-bit (n no. of bits in binary number). It is the extension to basic RCA concept, which scaled to handle any no of bits. The main building block of the RCA consists of Full Adders. As we know the Full Adder has three inputs as two operands and Carry input, and two outputs as Sum and Carry out. An n-bit RCA consists of chain of n Full adders (i.e. an 8-bit RCA consists of 8 Full Adder blocks. The RCA provides a n-bit Sum output and Carry output based on provided 2 n-bit operands and carry in signal usually zero (0).

A n-bit RCA does bit-wise addition of two operands using full adders, where the sum output of full adder will be summing output of corresponding bit and carry forwarded to next stage of full adder carry input. The term “Ripple” in RCA refers to the way of the carry propagation through the adders. The Carry out from the LSB adder ripples through the MSB of adder. This ripple propagation of carry causes delay proportional to the number of bits, making the adder slow for large width of bits. Whereas generally when we use an 8-bit RCA, and for addition of 16-bit operands we use RCA 2 times to save the area and provide performance. It is comparatively slower than CSA and CLA but design wise simplest among all other advanced n bit adders. Also, the hardware area is minimal as it comprises of series of full adders only.

The general time delay of Full Adders are as follows

$T_{sum}$  for sum calculation typically involves *XOR* gate, and  $T_{carry}$  for carry generation typically involves *AND* and *OR* gates. Now, for the time delay calculation of n-bit RCA, consists of n full adders. Each stage carry output propagated after  $T_{carry}$  delay hence n times  $T_{carry}$  (i.e.  $n * T_{carry}$ ). The sum output of corresponding bits available only after carry input of previous stage. The MSB calculated after  $n-1$  bit's carry out generation, hence we can say that for an n-bit RCA the time delay is given by following equation

$$T_{rca} = n * (T_{carry} + T_{sum}) \dots \quad 2.1.1$$

Assuming  $T_{\text{carry}} = T_{\text{sum}}$ , for 8-bit RCA we get delay of 16-units time.

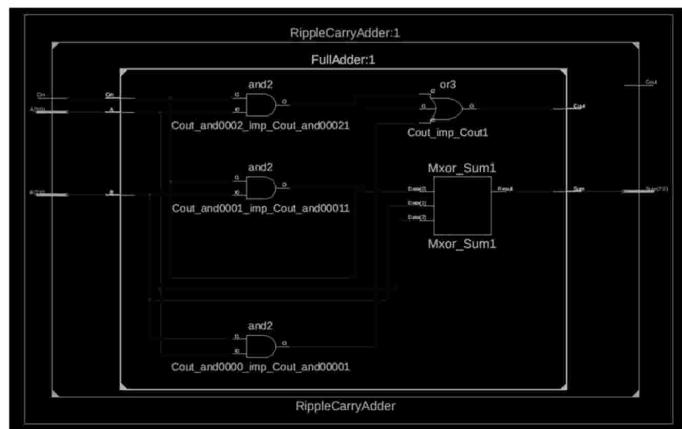


Fig 2.1.1 8-Bit RCA RTL From Xilinx Design Implementation

I have implemented 8-bit RCA during the internship also, implemented 4-bit design but showing results for 8-bit RCA only.

Here I have used the generate function in VHDL so by which in RTL view we can see that there is only one full adder block is being shown.

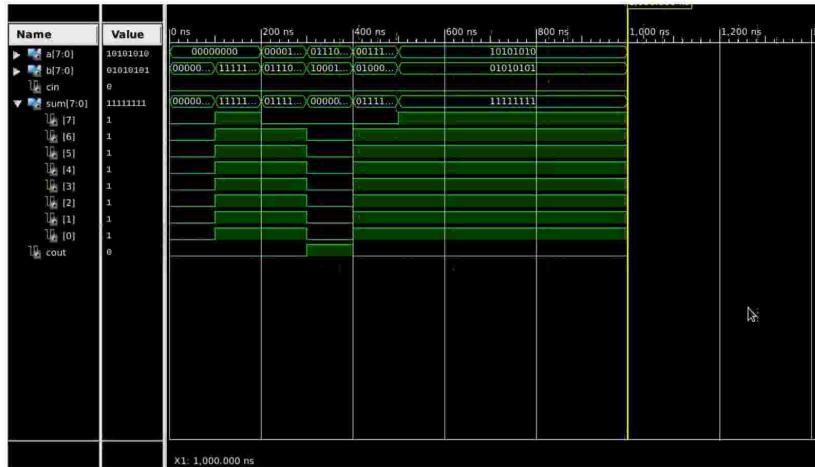


Fig 2.1.2 8-Bit RCA Simulation Output From Xilinx Design Implementation

RCA is basically used in simple arithmetic units where speed isn't the primary concern, for learning and educational purposes due to its basic simple design and used in those embedded systems where low power consumption and simplicity are more important parameters than speed.

### 2.1.2 Carry Look Ahead Adder (CLA)

Carry Look Ahead Adder is another kind of binary adder which is used in addition of more than 2-bit two operands. In comparison of RCA, it is faster but design is way more complex than that of RCA. The delay due to sequential carry propagation in RCA, is resolved in CLA by using a special combinational logic circuit. This Combinational circuit generates the carry of each stage in single machine cycle. The carry of each stage generated in advance.

The key concept of CLA is its different combinational logic circuit and partial full adder addition. The intermediate combinational circuit generates 2 signals i.e. G (generated carry bits) P (Propagated carry bits). The G signal is a bit position which generates carry if both corresponding bits of operands are logic high ‘1’, in Boolean logic expressed as

$$G_i = A_i \cdot B_i \dots \quad 2.1.2$$

The P signal is a bit position which generates carry if any of the corresponding bits if operands is logic high ‘1’, in Boolean logic expressed as

$$P_i = A_i + B_i \dots \quad 2.1.3$$

The Carry Look ahead logic generates the Carry signal of  $i^{\text{th}}$  bit in previous stage, with combinational logic of Boolean logic expressed as

$$C_{i+1} = G_i + P_i \cdot C_i \dots \quad 2.1.3$$

This combinational logic helps in generating carry parallelly reducing the delay of carry generation. The Corresponding Sum bits are generated with help of the xoring of corresponding bits of operands.

The output of all bits sums and final carry is generated in 4 machine cycles but, the only problem in CLA concept is the combinational logic for parallel carry generation requires an ‘*and gate*’ and ‘*or gate*’ of  $n+1$  inputs for  $n$ -bits width of CLA. i.e. for a 4-bit CLA in combinational logic stage it requires an ‘*and gate*’ of 5 inputs. By this the fan in and fan out delay by which indirectly we get propagational delays. Although this delay is smaller than RCA but the design complexity, costly design, power consumption causes its limitations for some other kinds of specific application.

Time delay calculation for CLA, here we have 3 different parts. i.e. G and P signal generation, Sum generation and Carry Calculation delay. For G and P, we can express delay by following equation

$$t_{G+P} = \max(t_{AND}, t_{OR}) \dots \quad 2.1.5$$

The sum calculation delay involves only xor gate delay hence we can express as

$$t_S = t_{XOR} \dots \quad 2.1.6$$

The Carry calculation involves multiple levels of ‘AND’ & ‘OR’ gates. For an n-bit CLA, the carry-out of the last bit involves a maximum of  $\log_2(n)$  levels of gates. By which we can express carry delay by the following equation

$$t_C = \log_2(n) * (t_{OR} + t_{AND}) \dots \quad 2.1.7$$

By all above 3 three equations the final delay for CLA n bit will be given by following equation

$$t_{CLA} = t_{XOR} + \log_2(n) * (t_{OR} + t_{AND}) + \max(t_{AND}, t_{OR}) \dots \quad 2.1.8$$

For example, in an 8-bit CLA all logic gates XOR, AND & OR having unit time delay, from the equation 2.1.8 we can say that 8-unit time delay.

I have implemented 8-bit CLA during the internship also, implemented 4-bit design but showing results for 8-bit CLA only. This implementation is similar kind as RCA. And design is extensible to 16-bits or any n-bit as designed with generate function.

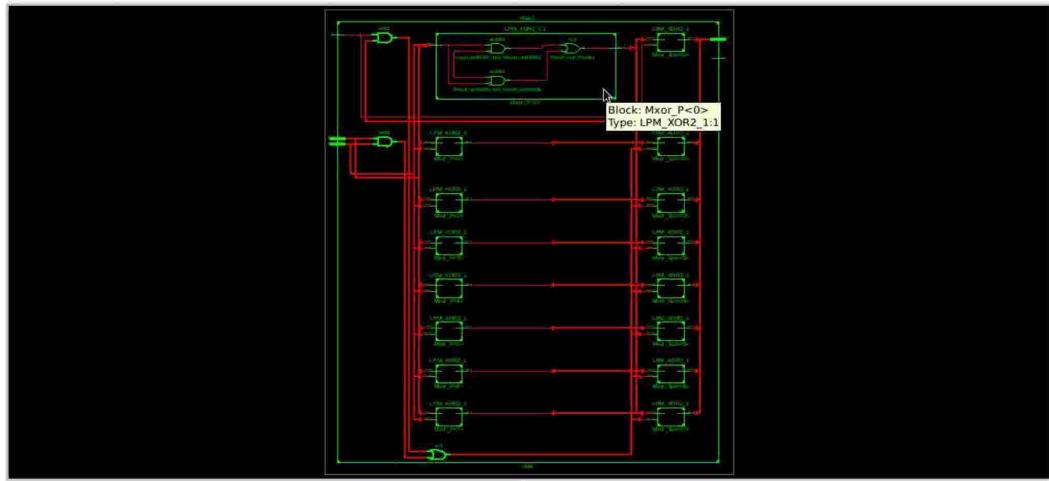


Fig 2.1.3 8-Bit CLA RTL From Xilinx Design Implementation

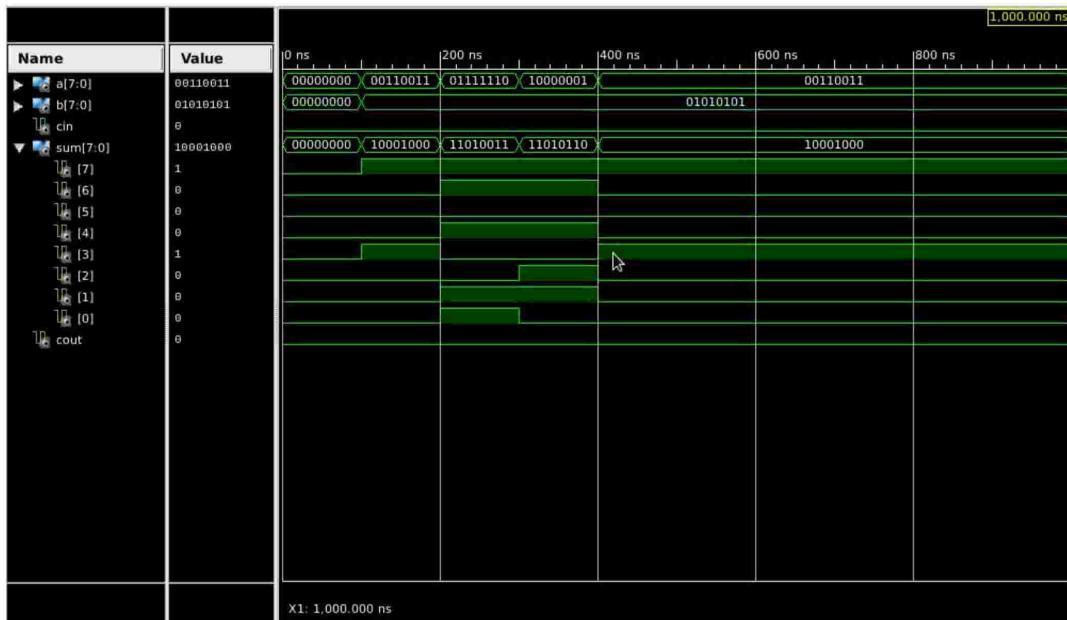


Fig 2.1.4 8-Bit CLA Simulation Output From Xilinx Design Implementation

### 2.1.3 Carry Save Adder (CSA)

A CSA is a type of binary digital adder used primarily in computer arithmetic operations. It is designed to add multiple operands simultaneously, which is particularly used in multiplication and accumulation operations. The CSA significantly speeds up the process.

by not propagating carry bits immediately but rather saving them for later addition. For an  $n$ -bits width CSA, the structure primarily consists of multiple stages of addition, where each stage handles the addition of three inputs and generates two outputs a sum of  $n$ -bits width and a carry bit. The key component of the CSA is basically a full adder.

For an n-bit CSA, in stage 1 of initial addition n Full Adders, each taking three input bits and generating n sum bits and n carry bits. In stage 2 of addition of sum and carry bits sum bits from the first stage are passed to the next stage and carry bits are shifted left and then added. This stage of shifting and adding continues until we have n-bit sum output and a single bit carry output.

Timing calculations for CSA, According to structure we have initially a full adder delay. Each full adder delay associated with generating sum and carry bit where, delay of full adder expressed by following equation

$$t_{FA} = t_{XOR} + t_{AND} + t_{OR} \dots \quad 2.1.5$$

The next delay is of CSA logic delay. The critical path delay is determined by the longest chain of carry propagation. For an n-bit CSA, the carry is not propagated immediately hence, the delay depends on the depth of carry-save stages. Now each stage involves full adder delays, typically uses  $\log_2(n)$  stages for adding n bits.

The final delay for adding n-bit three operands, the delay determined by the depth of stages and delay of a single full adder. The final delay expressed as following equation,

where  $k$  is the number of stages.

For example, by considering  $t_{FA} = 4$ -unit delay which consists 2-unit delay for XOR gate, 1 unit delay each for ‘AND’ and ‘OR’ gates. For an 8-bit CSA no. of stages in CSA is 3 from earlier discussion and final delay will be of 12-unit time only. Hence, we can conclude that The CSA is an efficient adder for handling multiple inputs simultaneously without the immediate carry propagation delay.

I have implemented 8-bit CSA design on Xilinx here are the results of following design implementations in figures.

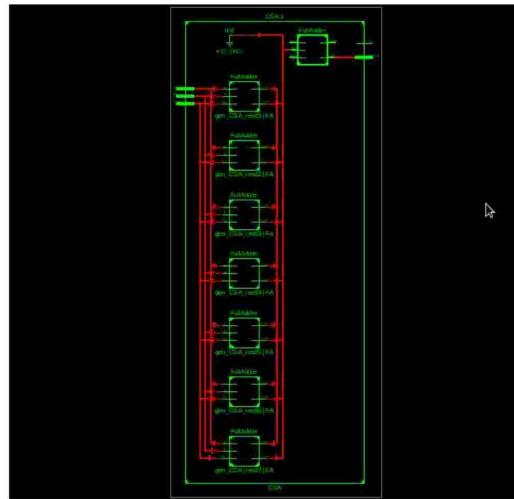


Fig 2.1.5 8-Bit CLA RTL From Xilinx Design Implementation

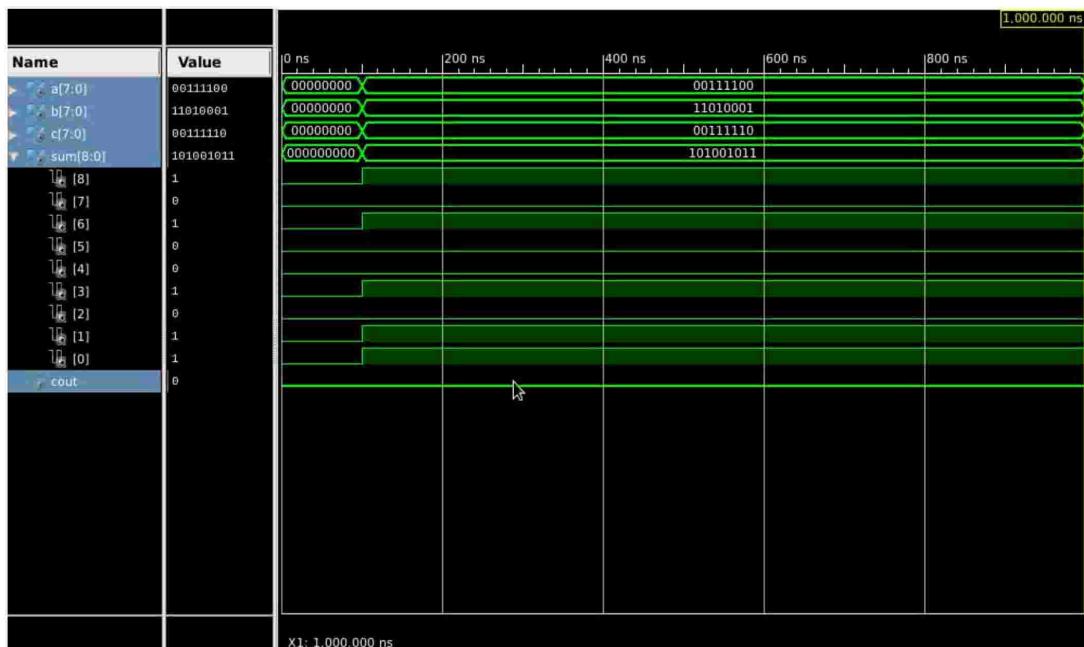


Fig 2.1.6 8-Bit CSA Simulation Output From Xilinx Design Implementation

#### 2.1.4 Comparison of Adders

Table 2.1 Comparison of adders.

Parameter	RCA	CLA	CSA
Basic Operation	Sequential carry propagation	Parallel carry computation	Saves intermediate carries for later addition
Sum Calculation	Sequential	Parallel	Parallel with multiple stages
Carry Calculation	Sequential	Parallel using generates and propagate signal	Saved for later stages
Gate count	Low	High	Moderate to High
Area	Small	Large	Moderate
Power Consumption	Low	High	Moderate
Speed	Slow	Fast	Fast in multi-operand addition
Complexity	Low	High	Moderate
Scalability	Poor	Good	Good
Example 8-bit delay	16 units	9 units	12 units

## 2.2 MULTIPLIER DESIGNS

Multipliers are fundamental components in digital electronics, used to perform arithmetic multiplication of binary numbers. They are essential in various applications such as digital signal processing (DSP), computer graphics, and general-purpose computing. The general types of multipliers used in digital electronics are Array Multipliers, Carry Save Array Multipliers, Wallace Tree Multipliers, Sequential Multipliers, Booth Multipliers, Pipelined Multipliers, Bit-Serial Multipliers. Among these Array Multipliers are most basic multipliers and used in understanding of Multipliers Functions. The multipliers used and

applied in different application on basis of their speed, efficiency, versatility, accuracy, integration etc. The general applications of multipliers are Digital Signal Processing, Computer graphics, Cryptography, Machine Learning, Embedded systems, etc.

### 2.2.1 Array Multipliers

Array Multipliers also known as Fast Multipliers are straight-forward and efficient method for performing binary multiplication. They use an array of adders to sum partial products generated by multiplying each bit of one operand by each bit of the other operand. Let's understand design a timing of 2-bit, 3-bit and 4-bit array multipliers and understand difficulties in n-bit multiplier designs.

In array multiplier the first stage to get partial products hence for a 2-bit array multiplier let's have 2 operands X and Y of 2 bits which generate the product of 4 bits.

Table 2.2 2-bit Multiplication

	X <sub>1</sub>	X <sub>0</sub>	<= Multiplicand operand
	×	Y <sub>1</sub>	Y <sub>0</sub> <= Multiplier operand
		X <sub>1</sub> Y <sub>0</sub>	X <sub>0</sub> Y <sub>0</sub> <= Partial products with Y <sub>0</sub>
C <sub>2</sub>	X <sub>1</sub> Y <sub>1</sub>	X <sub>0</sub> Y <sub>1</sub>	× <= Partial products with Y <sub>1</sub> and weigh added by 2 <sup>1</sup>
C <sub>2</sub>	X <sub>1</sub> Y <sub>1</sub> + C <sub>1</sub>	X <sub>1</sub> Y <sub>0</sub> + X <sub>0</sub> Y <sub>1</sub>	X <sub>0</sub> Y <sub>0</sub> <= Addition Results
P <sub>3</sub>	P <sub>2</sub>	P <sub>1</sub>	P <sub>0</sub> <= Product bits

In above calculation we can see that X is multiplicand and Y is multiplier. And we get product of 4-bits. There are 4 partial products in above multiplication by multiplying the bits Y<sub>0</sub> and Y<sub>1</sub> bitwise to X vector and we required 4 '*and gates*' for the partial product generation. Further in next stage the addition of each partial products with the corresponding weights is done and we get respective product bits generated. In this 2-bit array multiplier we have 2 half adders for addition as we have addition for P<sub>1</sub> bit partial products which generates the Carry C<sub>1</sub>, carried to the next stage and there another half adder

adds the next partial product and generated carry considered as 4<sup>th</sup> bit P<sub>3</sub>, of the product bits.

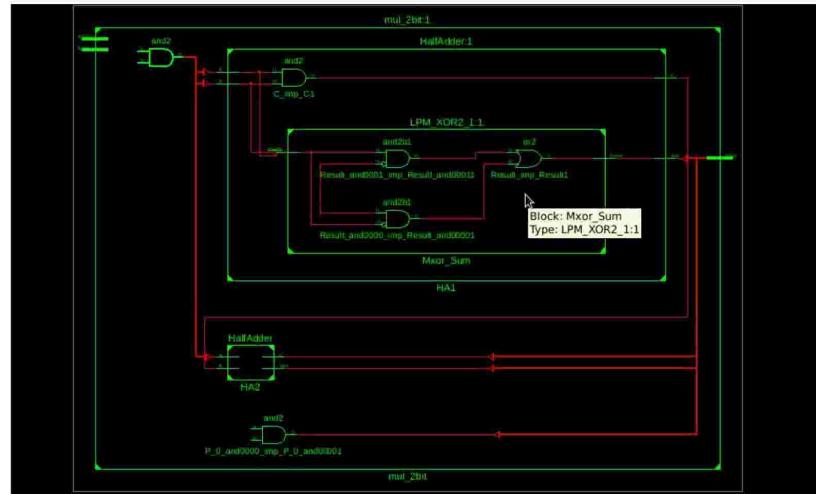


Fig 2.2.1 2-Bit Multiplier RTL From Xilinx Design Implementation

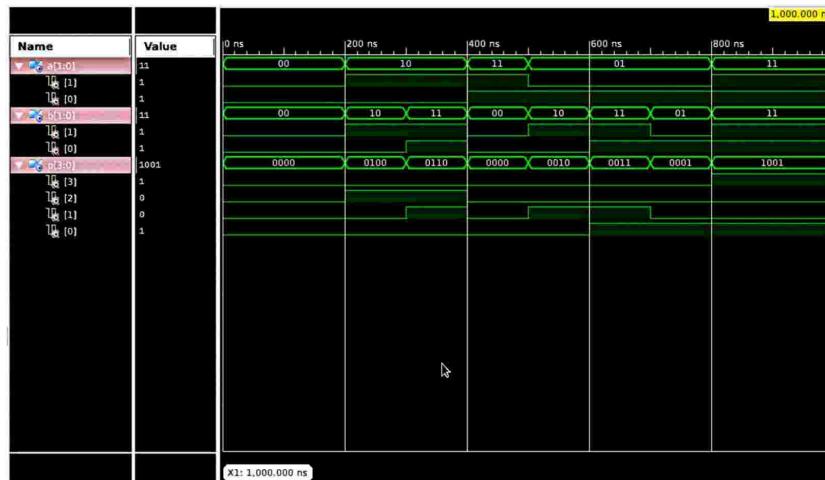


Fig 2.2.2 2-Bit Multiplier Simulation Output From Xilinx Design Implementation

Now in 3-bit fast multiplier let's see the design and the architecture. Similarly considering two 3 bits operands X and Y where X is multiplicand and Y is multiplier, and we have P vector of 6 bits.

Table 2.3 3-bit Multiplication

		X <sub>2</sub>	X <sub>1</sub>	X <sub>0</sub>	$\Leftarrow$ Multiplicand operand
	$\times$	Y <sub>2</sub>	Y <sub>1</sub>	Y <sub>0</sub>	$\Leftarrow$ Multiplier operand
		X <sub>2</sub> Y <sub>0</sub>	X <sub>1</sub> Y <sub>0</sub>	X <sub>0</sub> Y <sub>0</sub>	$\Leftarrow$ Partial products with Y <sub>0</sub>
		X <sub>2</sub> Y <sub>1</sub>	X <sub>1</sub> Y <sub>1</sub>	X <sub>0</sub> Y <sub>1</sub>	$\times$ $\Leftarrow$ Partial products with Y <sub>1</sub> and weigh added by 2 <sup>1</sup>
		X <sub>2</sub> Y <sub>2</sub>	X <sub>1</sub> Y <sub>2</sub>	X <sub>0</sub> Y <sub>2</sub>	$\times$ $\times$ $\Leftarrow$ Partial products with Y <sub>2</sub> and weigh added by 2 <sup>2</sup>
C <sub>23</sub>	X <sub>2</sub> Y <sub>2</sub>	X <sub>2</sub> Y <sub>1</sub> + C <sub>22</sub>	X <sub>1</sub> Y <sub>1</sub> + C <sub>21</sub> + C <sub>12</sub> + X <sub>1</sub> Y <sub>2</sub>	X <sub>1</sub> Y <sub>0</sub> + C <sub>11</sub> + X <sub>0</sub> Y <sub>1</sub>	X <sub>0</sub> Y <sub>0</sub> $\Leftarrow$ Addition Results and carry results where C <sub>1x</sub> shows the carry generated by addition at first stage and then C <sub>2x</sub> shows the carry generated by second stage of addition
P <sub>5</sub>	P <sub>4</sub>	P <sub>3</sub>	P <sub>2</sub>	P <sub>1</sub>	P <sub>0</sub> $\Leftarrow$ Product bits

In above calculation no. of adders may not be easy to find but no. of 'and gates' are clearly visible which is 9. For P<sub>0</sub> we don't require adder hence P<sub>0</sub> is directly fetched. Now for P<sub>1</sub> bit we must use a half adder as no carry in from previous stage. The Sum output of that half adder will be P<sub>1</sub> and Carry will be carried forward as C<sub>11</sub>. Now in next stage partial products and carry generated, added using full adders. And by reference to my circuit analysis during work I concluded that it requires 3 half adders and 3 full adders in structure.

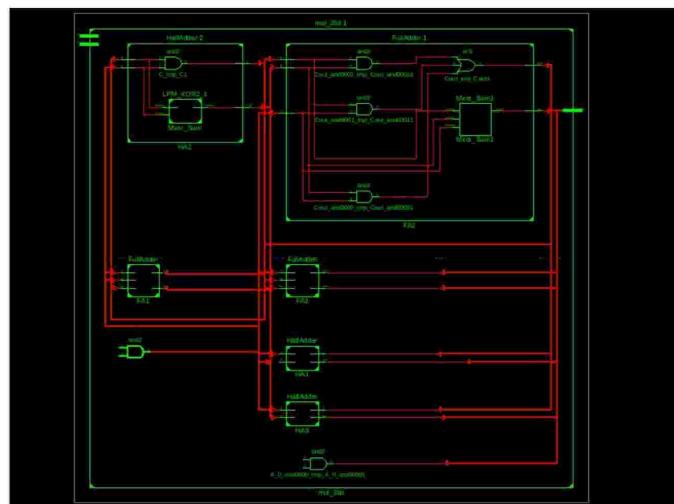


Fig 2.2.3 3-Bit Multiplier RTL From Xilinx Design Implementation

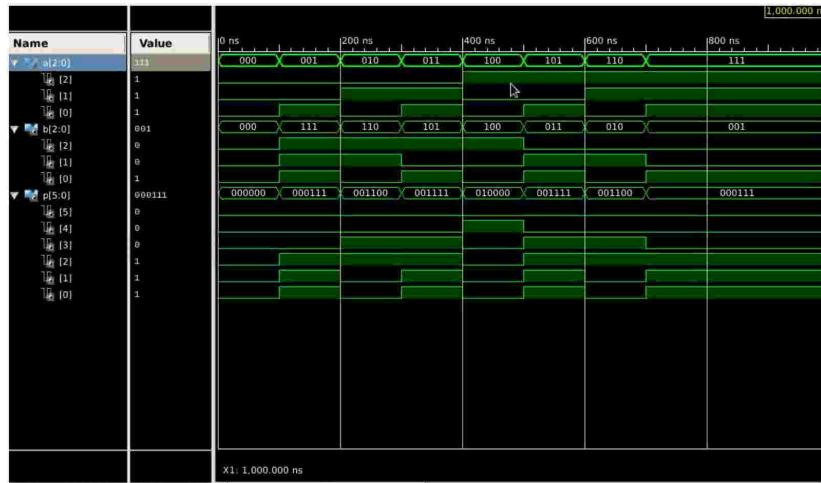


Fig 2.2.4 3-Bit Multiplier Simulation Output From Xilinx Design Implementation

Now let's see about 4-bit array multiplier. Similarly considering the A and B vector of 4 bits and output of 8 bits.

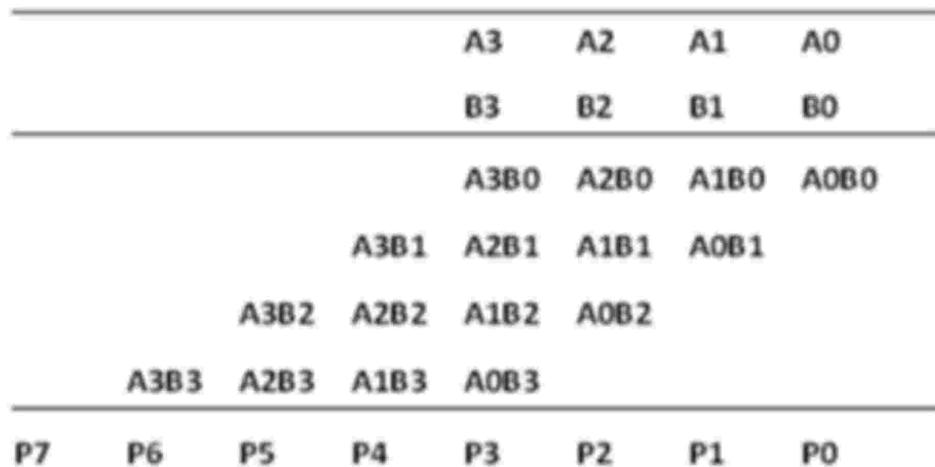


Fig 2.2.5 4-Bit Multiplier Multiplication Method

From reference to above figure, we can say that we require 16 '*and gates*' to get partial products. And with reference to my lab-work I concluded that it requires 4 half adders and 8 full adders. By which we can conclude for an n-bit multipliers no of required components given by following equations

No. of '*and gates*' =  $n^2$  ..... 2.2.1

No. of half adders =  $n$  ..... 2.2.2

No. of full adders =  $n(n-2)$  ..... 2.2.3

where  $n$  is width of input of operands of multipliers.

Now considering time delays taken by each multiplier and look at any kind of disadvantage.

For a 2-bit, 3-bit, 4-bit or  $n$ -bit multiplier design we require only 1 gate delay for partial products. Now for 2-bit multiplier we have 2 half adders and the 2<sup>nd</sup> half adder is dependent on 1<sup>st</sup> adder for carry. Let's consider 2-unit delay required to propagate carry from 1<sup>st</sup> half adder hence total delay will be of 5-unit (i.e. 1+2+2).

Now in case of 3-bit multiplier in addition we have 3 levels 1<sup>st</sup> for half adder with 1-unit delay. 2<sup>nd</sup> level of full adders for intermediate stage with 2-unit delay. And similar at final stage 3<sup>rd</sup> level of 2-unit delay. The total delay about of 6-unit time. Similarly in case if 4-bit multiplier we have final level of adders in 4<sup>th</sup> stage hence the total time delay can be of 8-unit times.

The design constraint of this fast multipliers or array multipliers is no. of logic and gates and full adder blocks required to get a design for  $n$ -bit width. Such as for a 8-bit array multiplier we need 64 '*and gates*' and about 8 half adders and 48 full adders for simplicity if we use all full adders implementation then also we require 56 different full adders as design of such array multiplier in VHDL is not easy because we can't use generate logic for addition stage. Also, the chip size and power consumption increase with increase in width of multiplier input. Now let's see the design implementation of 4-bit multiplier on Xilinx.

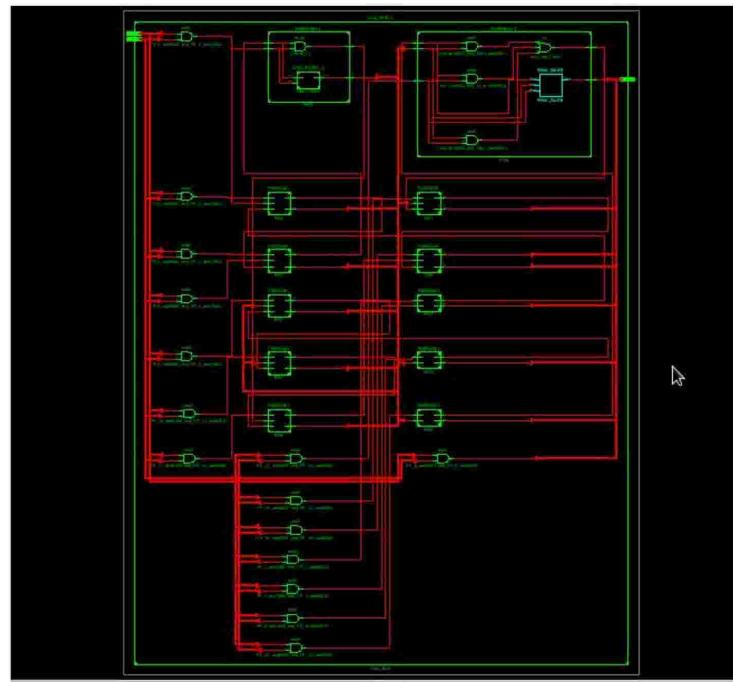


Fig 2.2.6 4-Bit Multiplier RTL From Xilinx Design Implementation

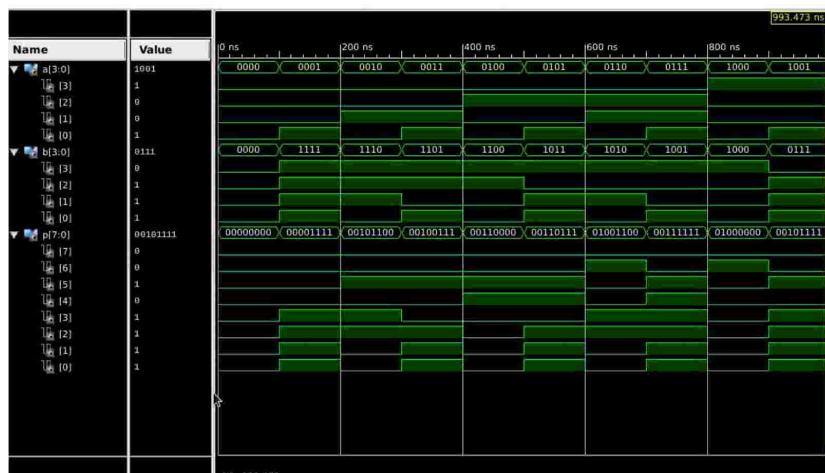


Fig 2.2.7 4-Bit Multiplier Simulation Output From Xilinx Design Implementation

### 2.2.2 Booth Multipliers

Booth multiplier is kind of multiplier works on basis of booth's algorithm of multiplication that multiplies two signed binary numbers in 2's complement notation. Booth uses desk calculators that were faster at shifting than adding and created the algorithm to increase the speed and performance of the multiplier. This multiplier is used more due to its ease in scaling and faster multiplication. Also, the design is not that complex as compare to fast multipliers.

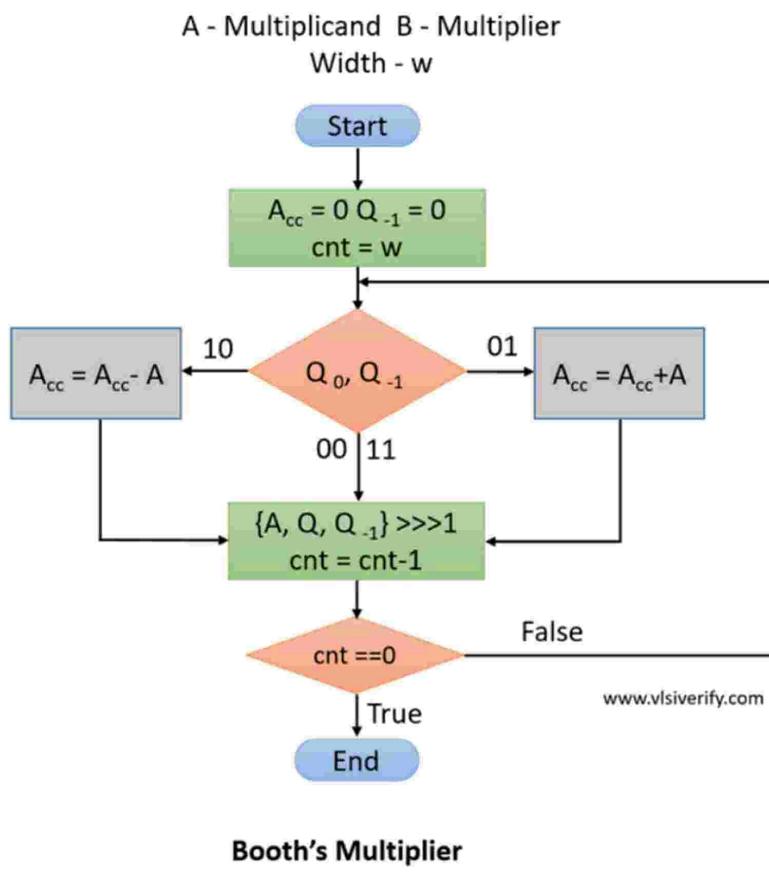


Fig 2.2.8 Booth's Algorithm Flow Chart

Here A is the input operand Multiplicand, B is the multiplier operand. Q register is initially same as B,  $Q_0$  holds the LSB of the Q register.  $Q_{-1}$  is a 1 bit variable or register. Acc is Accumulator register for holding result of intermediate addition and subtraction. Count holds the maximum width of multiplicand or multiplier.

The disadvantages of booth logic are high power consumption and larger chip area occupation. Even though these disadvantages we use Booth Multiplier in few applications such as Arithmetic units, DSP, Scientific computing and machine learning and neural networks.

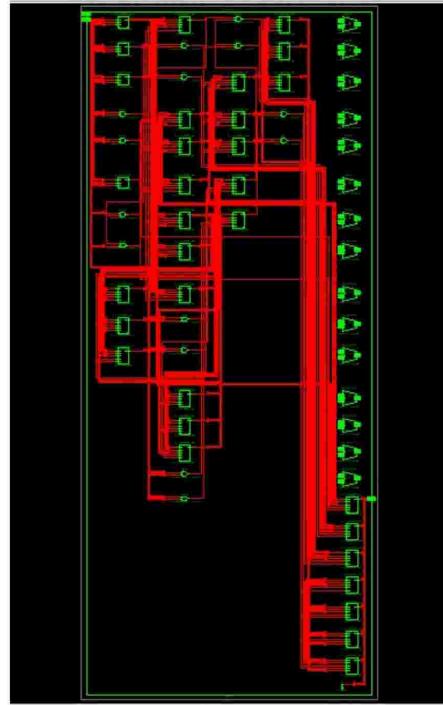


Fig 2.2.9 8-Bit Booth Multiplier RTL From Xilinx Design Implementation



Fig 2.2.10 8-Bit Booth Multiplier Simulation Output From Xilinx Design Implementation

### 2.2.3 Multipliers Comparison

Table 2.4 Comparison of Multipliers

Parameter	Booth Multiplier	Array Multiplier
<b>Algorithm</b>	Booth's Algorithm	Partial product addition
<b>Basic Operation</b>	Encoding and reducing number of additions	Summing partial products
<b>Handling signed numbers</b>	Efficiently handles signed numbers	Requires separate handling of sign
<b>Number of operations</b>	Reduces operations for sequences of 1's	Number of operations proportional to $n^2$
<b>Speed</b>	Faster for large no. of consecutive 1's	Slower for large bit-widths
<b>Hardware Complexity</b>	More complex	Simple straight forward
<b>Scalability</b>	More scalable	Less scalable
<b>Power consumption</b>	Lower	Higher
<b>Efficiency</b>	More in certain patterns	Uniform performance
<b>Implementation</b>	More complex logic control	Simple repetitive
<b>Best use case</b>	Signed multiplication large bit-widths	Smaller bit-widths, simpler applications

## CHAPTER 3: VLSI PHYSICAL DESIGN FLOW

### 3.1 INTRODUCTION

After design implementation on Xilinx and having RTL of combinational logic circuits, we require a physical chip or IC fabricated and packaged to use it in day-to-day life. As I discussed earlier in introduction chapter that SoC are designed and fabricated to use in mobile phones. That IC is first having architectural design in three domains of VLSI design flow, physical, behavioral, structural domains. Then the fabrication of IC is done. We till now done design implementation in behavioral domain and structural domain to check whether our thoughts or idea can give the similar output as our requirement. Now we will explore about physical domain. The Geometrical design or Layout design is done in physical domain. This process done in sophisticated software tools called as Electronics Design Automation (EDA) or CAD tools. The software EDA tool we used for physical layout is OpenROAD. Now let us explore more about OpenROAD tool next section.

### 3.2 INTRODUCTION TO OpenROAD EDA TOOL

The OpenROAD EDA tool is Linux based opensource tool which is used to generate RTL-GDSII layout of Verilog language designed entities or modules. If we talk about OpenROAD tool then it consists of various tool chain for different steps of the RTL-GDSII flow layout planning. This chain of tools is called as OpenROAD-flow-scripts (ORFS). The ORFS consists of Magic, Yosys, OpenSTA, iverilog, gtkwave, klayout, OpenLane, OpenROAD. Each tool has its own use in different stages of RTL-GDSII flow. Likewise Magic and Klayout are for layout planning. Yosys used as logic synthesis tool which synthesizes the raw verilog file to required SDC file for next steps of routing, netlisting and floorplanning of ICs. Earlier stages there was no tool for clock tree synthesis but now we have tools like OpenSTA or OpenCLOCK for static timing analysis and clock tree synthesis. iverilog tool used to have HDL simulations inside the ORFS. gtkwave is waveform viewer. And at last, the main OpenROAD or OpenLane where we call all this tools by its GUI and command prompt window in GUI. Let us see how we can install and use all those tools to design IC from RTL to GDSII.

### **3.1 Step-by-step Installation Process.**

The basic required system for using ORFS is Ubuntu Linux Based System. For latest Ubuntu 24.04 LTS we require at least 8 GB RAM recommended along with 100 GB of free space HDD or SSD and a quad processor with 2.4 GHz clock or better than that. A stable internet connectivity is also recommended probably ethernet or Wi-Fi as software installation is become bad to worst if internet is not working properly and may stuck in between any step of installation process. A dual boot laptop or desktop, or an ubuntu based system is required, do not try, or waste your time trying any other methods of Linux installation in your system such as WSL or VMBox. Simply install ubuntu linux in your system and do the step to install ORFS.

To install Ubuntu 24.04 by your own efforts you should have to create bootable pen-drive of 16 GB, and Then by entering to BIOS setup doing some changes you will be able to do boot in Ubuntu and Windows on single system. After installation of Ubuntu do 2 to 3 times of check of booting and try to install ORFS after 4 to 5 hours of installation of Ubuntu in system, if you using your old Ubuntu system then you can go through the installation steps as given below.

Installation steps for ORFS are as follows

Step 1:

Open the command terminal upgrade, and update the packages and whole ubuntu for new releases may required in further steps by using command **sudo apt-get update, sudo apt upgrade** (reboot recommended after packages upgradation)

Step 2:

Install the git package which will be used to clone GitHub repositories to your system by using the command, **sudo apt install git –assume-yes**

Step 3:

Install the dependencies and build essential by prompting command, **sudo apt install -y build-essential**

Step 4:

Install the Python using following command, `sudo apt install -y python3-venv`

Step 5:

Next step is to make the default ‘sh’ to be ‘bash’ rather than ‘dash’ you can do it by following command, `sudo rm /bin/sh && sudo ln -s /bin/bash /bin/sh`

Step 6:

After that you should create directory or work area in ubuntu for ORFS by using following command, `mkdir -p Work/vlsi/tools`

Step 7:

Now we will move to tools directory and install Yosys and OpenROAD in that directory.

The command should be followed as given, `cd ~/Work/vlsi/tools`

`git clone --recursive https://github.com/The-OpenROAD-Project/OpenROAD-flow-scripts`

Step 8:

Setup of OpenROAD and Yosys by following command, `mkdir Open-ROAD-flow-scripts, cd ~/Work/vlsi/tools/OpenROAD-flow-scripts, sudo ./setup.sh`

Step 9:

Installation of OpenROAD and Yosys by following command, `./build_openroad.sh – local` (this step will take about 30-40 minutes to install without any error).

Step 10:

Installation of dependencies of Magic VLSI tool by using following commands, `cd && sudo apt-get update && sudo apt-get install m4 --assume-yes && sudo apt-get install tcsh --assume-yes && sudo apt-get install csh --assume-yes && sudo apt-get install libx11-dev --assume-yes && sudo apt-get install tcl-dev tk-dev --assume-yes && sudo apt-get install libcairo2-dev --assume-yes && sudo apt-get install mesa-common-dev libglu1-mesa-dev --assume-yes && sudo apt-get install libncurses-dev --assume-yes`

Step 11:

Installing Magic VLSI tool by using following command as given below, `git clone https://github.com/RTimothyEdwards/magic.git && mkdir yosys && cd yosys && sudo make && sudo make install` (this process of installation may take 30-45 minutes depending on stability and connectivity of internet you providing).

Step 12:

Installation of the iverilog tool for HDL simulations in ORFS,  
**sudo apt-get install -y iverilog –assume -yes**

Step 13:

Installation of the gtkwave waveform simulation tool in ORFS,  
**sudo apt install gtkwave –assume -yes**

Step 14:

Installation of the Klayout, layout planning toll in ORFS,  
**sudo apt install klayout –assume -yes**

Step 15:

Installation of docker in ubuntu to install the OpenLane by docker method,

```
sudo apt-get remove docker docker-engine docker.io containerd runc –assume-yes
sudo apt-get update –assume-yes
sudo apt-get install\ apt-transport-https\ca-certificates\curl\gnupg\lsb-release –
assume-yes
curl-fsSL https://download.docker.com/linux/ubuntu/gpg | sudo gpg --dearmor -
o/usr/share/keyrings/docker-archive-keyring.gpg –yes
echo\ “deb [arch=amd6 signed-by=/usr/share/keyrings/docker-archive-
keyring.gpg] https://download.docker.com/linux/ubuntu\\$\(lsb\_release -cs\) stable" | sudo tee /etc/apt/sources.list.d/docker.list >/dev/null
sudo apt-get update –assume-yes
sudo apt-get install docker-ce-cli containerd.io –assume-yes
```

Step 16:

Installation of OpenLane tool under the ORFS tool chain,

```
cd
git clone https://github.com/The-OpenROAD-Project/OpenLane.git
mkdir OpenLane
cd OpenLane
sudo make
sudo make install
```

By following above steps, we can install all the required tools for the ORFS tool chain, now we can proceed the step to install the opensource PDK supported by OpenROAD which will provide design constraints and standard cell library for our design implementation. By default, with OpenLane and ORFS we get skywater130 PDK and nangate45 PKD support, for other PDKs such as GF180MCU, SKY90FD, GlobalFoundries are such PDKs.

The installation of the PDK in the system is not that tough you can go through website link given below to install PDKs the link for installation process is:  
[http://www.opencircuitdesign.com/open\\_pdks/install.html](http://www.opencircuitdesign.com/open_pdks/install.html)

After installation of all the tools we need to verify either all the tools are successfully installed or not. These current steps support verilog language synthesis only. For implementing and synthesis of VHDL modules in yosys gnat and ghdl, so that we can use VHDL files and parse for synthesis.

### **3.2 Installation Verification Process.**

To verify the installation of ORFS tools the best is to use them directly or simply enter each command one by one by which information of the this ORFS tools or version may be visible to you in terminal or if the version or information is not visible then you must reinstall the respective tool by following respective step mentioned above again. The command to verify each tool installation given in following table.

Table 3.1 Command table for verification

<b>Command</b>	<b>Command Output</b>
yosys -V	Version of yosys installed will be displayed
openroad -version	Version of openroad will be visible
gtkwave -v	gtkwave installed version will be displayed
iverilog -V	iverilog installed version will be displayed
docker --version	docker version will be displayed
opensta	either GUI of opensta or information will be displayed

<code>klayout -v</code>	klayout version will be displayed
<code>magic --version</code>	magic tool installed version will be displayed
<code>./flow.tcl -help</code> (this command should be used by moving to OpenLane directory and then run this command)	This will display the information of OpenLane flow script.
<code>ls \$PDK_ROOT/sky130A</code> or <code>ls \$PDK_ROOT/pdk_name</code>	This will list the content of PDK directory.

### 3.3 RTL TO GDSII FLOW

The ORFS has different tools by which we can go through RTL to GDSII flow easily if we provide proper parameters and PDK files. Later, we will discuss about how we can get RTL to GDSII step by step. Now let us understand about what is RTL to GDSII flow. The ORFS is autonomous software but we will use it in manual order step by step to debug in between any error. Now see the flow of RTL to GDSII in following figure.

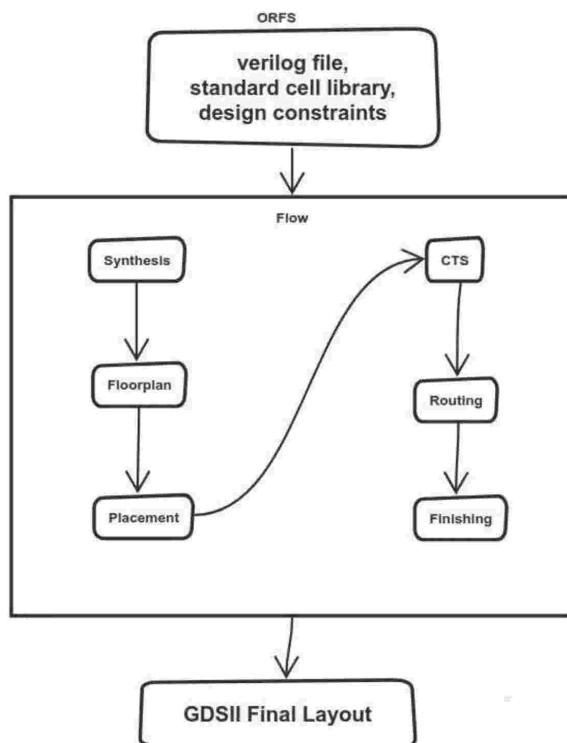


Fig 3.3.1.a RTL to GDSII Design Flow

As per the last figure we need to create a verilog file, and then from PDK we must select any PDK and then use that PDK's library file and design constraint file during the synthesis process through the yosys.

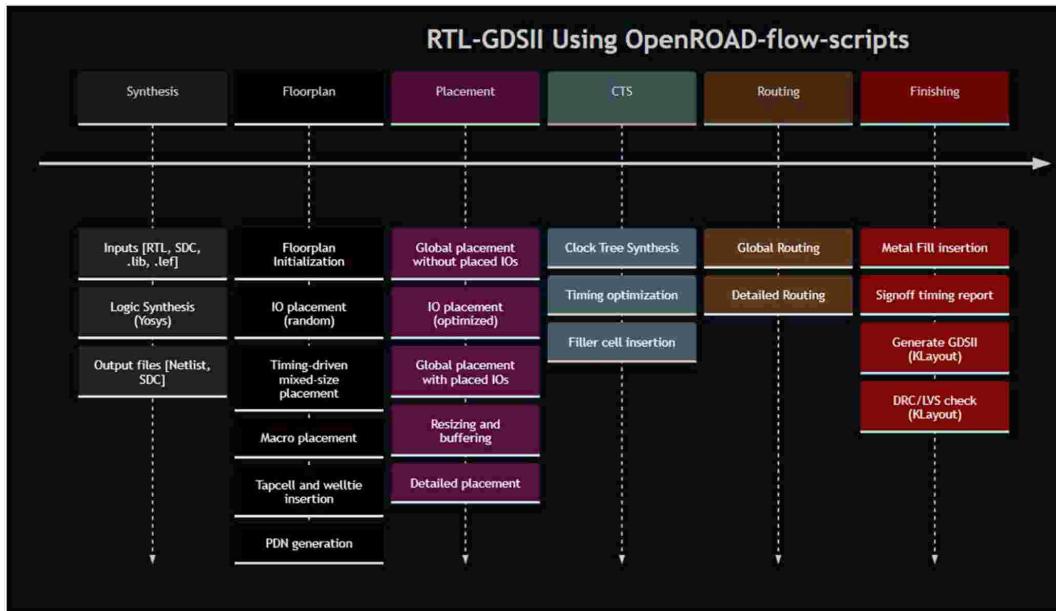


Fig 3.3.1.b RTL To GDSII Flow Using ORFS

Now let us understand about each part of Physical design flow given in figure 3.3.1.b

**Synthesis:** The process of synthesis is to synthesize the netlist file of the module using selected standard cell library provided by the vendor. The input of the synthesizer used yosys in the ORFS are verilog file and standard cell library which gives output of Gate level netlist and SDC of the designed module.

**Floorplan:** The Floorplan will initiate the basic area of die and core which will be used to design on actual silicon substrate. It helps in random IO placement which further rectified according to design and tapcell insertion for the design.

**Placement:** The placement in RTL to GDSII consists of many parts such as Global cell placement, IO placement, Global Placement with placed Ios, Resizing and buffer settings and detailed placement, provides various parameters and organizes the different objects such as IO pins, Buffers placement and give proper distribution.

**Clock Tree Synthesis:** This is done with help of opensta tool, which is used whenever we have any kind of clock driven part inside the chip and it will help in dividing the clock and proper clock functioning.

**Routing:** This part helps in interconnections between vias and metals layers of the different layers and interconnections between different blocks of design inside the chip.

**Finishing:** In general, wherever we are using checkpoint, report and repair we are checking for any kind of faults and error in design which is termed as Finishing of design.

Now let us see the step-by-step process of getting RTL to GDSII final layout from a verilog file.

Design realization and implementation by using PDK of vendor nangate45 which support 45nm technology window design, and consist of design constraints and standard cell library for design implementation. The PDK will be provided by the vendor from whom you wished to fabricate your IC, here we are using open-source PDK for our designs

**Note:-** Commands and outputs are in Italic and Bold. Also due to irregularity in sentence width the justify alignment isn't used during the steps as it seems too bad format, as of example you can see the above paragraph ending.

Step 1: To create a verilog file you can use by default text editor and save it in any folder in home directory or if you installed by following our method then you can do it by saving it in tools folder's any new folder, along with .v extension.

Step 2: Open terminal and write command: **yosys**. To access the yosys for synthesis.

Step 3: Open your verilog file by using command: **read\_verilog /\$file\_path/file\_name.v**  
**read\_verilog /home/darshit-mehta/run01/CarryLookAheadAdder\_8bit.v**  
In this step we will get output message on terminal as  
***Generating RTLIL representation for module `CarryLookAheadAdder\_8bit'.***  
***Successfully finished Verilog frontend.***

Step 4: Checking, expanding, and cleaning of the design hierarchy, which will be done by following command: **hierarchy -check -top CarryLookAheadAdder\_8bit**  
By performing this step you will get the output such that  
***analyzing design hierarchy..***  
***Top module: \ CarryLookAheadAdder\_8bit***  
***Removed unused 0 modules***

**Note:-** The setup we got limitation of setting only one entity module, if your verilog code has more than one entity module then you may get error at previous step or any of the next step. Hence to ensure the least error chances implement your design based in basic gates rather than using more than one entity.

Step 5:Conversion “processes” into multiplexers and registers (the internal representation of behavioral verilog code) by using command: ***proc*** . After this you should wait until any error message shows or proceed to next step if no error message shows.

Step 6:Perform some basic optimizations and cleanups by using following command: ***opt***  
This will show message at last that ***Finished OPT passes. (There is nothing left to do.)***

After getting this message you can proceed to next step.

Step 7:Analyze and optimize finite state machine for your design by using following command: ***fsm***

By following this step you get last message as

***Executing FSM\_MAP pass (mapping FSMs to basic logic).*** After this repeat Step 6.

Note: From this onward after every step, it is good practice to use command: ***opt*** for performing basic optimization and cleanups.

Step 8:Analyze memories and create circuits to implement them for your design by using following command: ***memory***

This kind of message will be shown in ending if this process

***Executing MEMORY\_MAP pass (converting memories to logic and flip-flops).***

Step 9:Map coarse-grain RTL cells (adders, etc. ) to fine-grain logic gates (AND ,OR ,NIT,ETC...) by using following command: ***techmap***

***Successfully finished Verilog frontend.*** This message may be displayed or if you get any error you can restart process or debug it if error is understandable.

Step 10:Map registers to available hardware flip-flop from lib by using following command: ***dfflibmap -liberty /home/darshit-mehta/Work/vlsi/tools/OpenROAD-flow-scripts/tools/OpenROAD/test/Nangate45/Nangate45\_typ.lib***  
***\$/home/darshit-mehta/Work/vlsi/tools/OpenROAD-flow-scripts/tools/OpenROAD/test/Nangate45*** this is the file path of standard cell library provided by vendor. Wait till the process end and proceed to next step.

Step 11:Map logic to available hardware gates by using the command:

***abc -liberty /home/darshit-mehta/Work/vlsi/tools/OpenROAD-flow-scripts/tools/OpenROAD/test/Nangate45/Nangate45\_typ.lib***

By performing this step you will message displaying some useful information.

***Re-integrating ABC results.***

***ABC RESULTS: NAND2\_X1 cells: 3***

***ABC RESULTS: AOI21\_X1 cells: 3***

***ABC RESULTS: AND2\_X1 cells: 4***

***ABC RESULTS: OR2\_X1 cells: 4***

<b>ABC RESULTS:</b>	<i>AOI221_X1 cells:</i>	<b>1</b>
<b>ABC RESULTS:</b>	<i>NOR2_X1 cells:</i>	<b>5</b>
<b>ABC RESULTS:</b>	<i>XOR2_X1 cells:</i>	<b>4</b>
<b>ABC RESULTS:</b>	<i>OAI21_X1 cells:</i>	<b>4</b>
<b>ABC RESULTS:</b>	<i>XNOR2_X1 cells:</i>	<b>12</b>
<b>ABC RESULTS:</b>	<i>internal signals:</i>	<b>115</b>
<b>ABC RESULTS:</b>	<i>input signals:</i>	<b>17</b>
<b>ABC RESULTS:</b>	<i>output signals:</i>	<b>9</b>

**Removing temp directory.**

Step 12: Next step is to flattening of design using command: ***flatten***

Executing FLATTEN pass. (flatten design) {This message may be seen}

Step 13: Replacement of undef values with defined constants this is important as if we don't do this then our design may get any error in any next step. The command for this task is : ***setundef -zero***

Step 14: Removal of unused cells and wires is also important to optimize our design, The command for this task is: ***clean -purge***

Step 15: Next step is technological mapping of i/o pads (or buffers) by using the command: ***iopadmap -outpad BUF\_X2 A:Z -bits***

Step 16: Use command : ***clean*** . To remove unused cells and wires.

Step 17: To do some important calculations such as die area or core area of IC we require some stats this statistics data obtain by using command: ***stat -liberty***

*/home/Darshit-mehta/Work/vlsi/tools/OpenROAD-flow-scripts/tools/OpenROAD/test/Nangate45/Nangate45\_typ.lib*

Here “/home/darshit-mehta/Work/vlsi/tools/OpenROAD-flow-scripts/tools/OpenROAD/test/Nangate45/Nangate45\_typ.lib” is path of the standard cell library file, which will give stats related such as no. components, wires, cells, processes and at last the chip area value in micrometers<sup>2</sup> units. This will determine the chip core area and die area in substrate during fabrication process.

Printing statistics.

**==== CarryLookAheadAdder\_8bit ===**

<b>Number of wires:</b>	<b>38</b>
<b>Number of wire bits:</b>	<b>66</b>
<b>Number of public wires:</b>	<b>5</b>
<b>Number of public wire bits:</b>	<b>26</b>
<b>Number of memories:</b>	<b>0</b>
<b>Number of memory bits:</b>	<b>0</b>

<i>Number of processes:</i>	<b>0</b>
<i>Number of cells:</i>	<b>49</b>
<i>AND2_X1</i>	<b>4</b>
<i>AOI21_X1</i>	<b>3</b>
<i>AOI221_X1</i>	<b>1</b>
<i>BUF_X2</i>	<b>9</b>
<i>NAND2_X1</i>	<b>3</b>
<i>NOR2_X1</i>	<b>5</b>
<i>OAI21_X1</i>	<b>4</b>
<i>OR2_X1</i>	<b>4</b>
<i>XNOR2_X1</i>	<b>12</b>
<i>XOR2_X1</i>	<b>4</b>

***Chip area for module 'CarryLookAheadAdder\_8bit': 59.052000***

This will be displayed message may vary according to your components.

Step 18: Rename the object in the design is the next step , we can assign short auto-generated names to all the selected wires and cells with private name or use this command: **rename -enumerate** to do same.  
 Overwriting the design to verilog file is also included in this step this is done by using command: **write\_verilog -noattr CarryLookAheadAdder\_8bit1\_final.v**

Step 19: Now to generate BLIF file or netlist we must use the following command:

**write\_blif -buf BUF\_X2 A Z  
*CarryLookAheadAdder\_8bit1\_mapped\_withbuf.blif***

Step 20: Now we should check the netlist generated and stored in BLIF file by previous step with help of graphviz, it will generate schematic graph of our netlist. This can be done by using command: **show -stretch**  
 In this step you will be able to see the netlist as shown in figure.

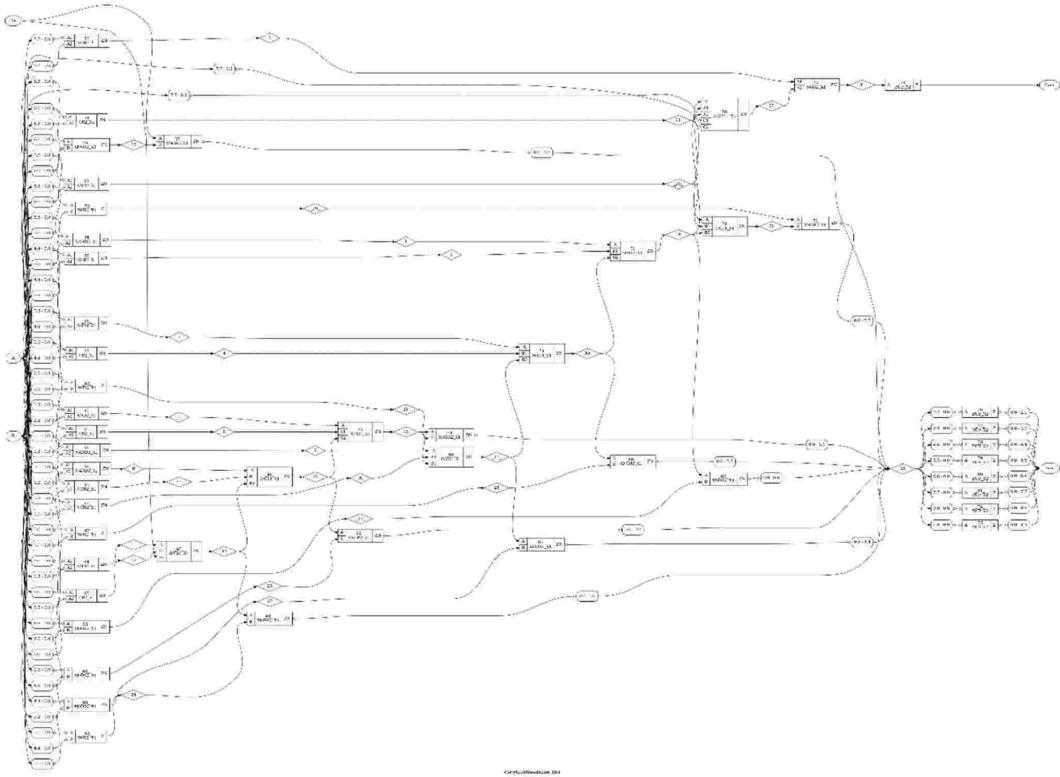


Fig 3.3.2 RTL to Gate Level Netlist of CarryLookAheadAdder\_8bit

Step 21: Now you have exit the yosys using command: ***exit***, and interact with Openroad GUI by using command: ***openroad -gui***

Note: Until this step we were working over yosys the synthesis tool now we must go for further steps to generate final GDS layout using OpenROAD tool of ORFS. The GUI of OpenROAD is command line-based tool hence at each step has different commands, the commands will be same font as until we see in previous steps.

Step 22: Create a SDC file with text editor and give name as SDC and save in .csv extension.

This file also in same directory where you have previously saved verilog file. You may notice some changes that verilog file if you did not save the synthesized verilog file in different name. The content of SDC file is  
***create\_clock [get\_ports clk] -name core\_clock -period 0.4850***  
***set\_all\_input\_output\_delays***

Now you must save this SDC file and final verilog file in folder with following path, \$/home/darshit-mehta/Work/vlsi/tools/OpenROAD-flow-scripts/tools/OpenROAD/test . After that you may proceed for further steps.

Note: The chip area will give you idea about estimation of chip area and die area, You can either you can keep same as chip area or round it to nearest ten for sake of simplicity and for larger areas you have to choose area by trial and error method. Although we have a

relation that if  $u$  = utilization efficiency of chip, then die area =  $(\text{chip area} * 100) / u$ , where  $u$  ranges between 30% to 90% practically may more different. And according to die area you can set core area.

Step 23: Now we will put following commands in command prompt of openroad GUI.

```
set design "CarryLookAheadAdder_8bit"
set top_module "CarryLookAheadAdder_8bit"
set synth_verilog "CarryLookAheadAdder_8bit1_final.v"
set sdc_file "CarryLookAheadAdder_8bit.sdc"
#set die_area {0 0 42 42}
set die_area {0 0 42 42}
#set core_area {2.5 2.5 40 45}
set core_area {2.5 2.5 40 45}
```

After having this command in the command window now you can press enter to set these parameters to the openroad for the design.

Step 24: In this step you have to give command of reading the design files to the openroad by using commands given below,

```
read_libraries
read_verilog $synth_verilog
link_design $top_module
read_sdc $sdc_file
```

Step 25: In this step we will having STA network instance count for all other parameters required to generate the final layout, this step will help in creating all other parameters.

```
utl::metric "IFP::ord_version" [ord::openroad_git_describe]
# Note that sta::network_instance_count is not valid after tapcells are added.
utl::metric "IFP::instance_count" [sta::network_instance_count]
```

Step 26: In this step we will initiate process of floorplanning.

```
initialize_floorplan -site $site \
-die_area $die_area \
-core_area $core_area
```

By which you will get floorplan figure.

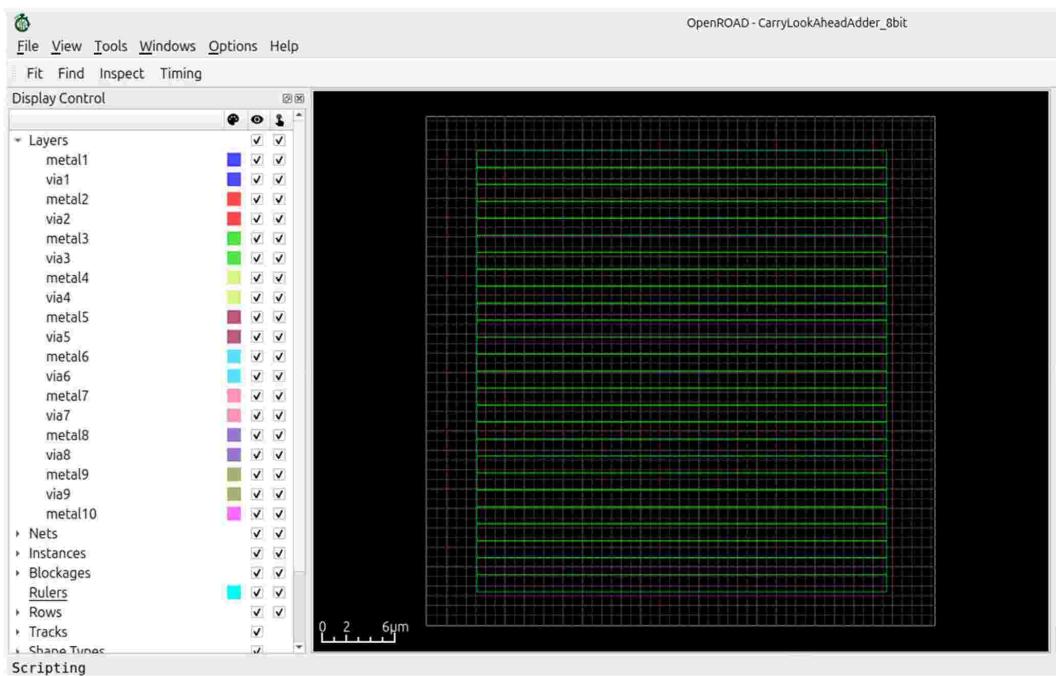


Fig 3.3.3 Floorplan Command Output Window.

Step 27: Now to optimize the design we must remove unused or unrequired buffers by using commands,

```
source $tracks_file
# remove buffers inserted by synthesis
remove_buffers
```

We will get output at output console: **[INFO RSZ-0026] Removed 16 buffers.**

Step 28: Now next step is random IO placement by using the following commands

```
# IO Placement (random)
place_pins -random -hor_layers $io_placer_hor_layer -ver_layers
$io_placer_ver_layer
```

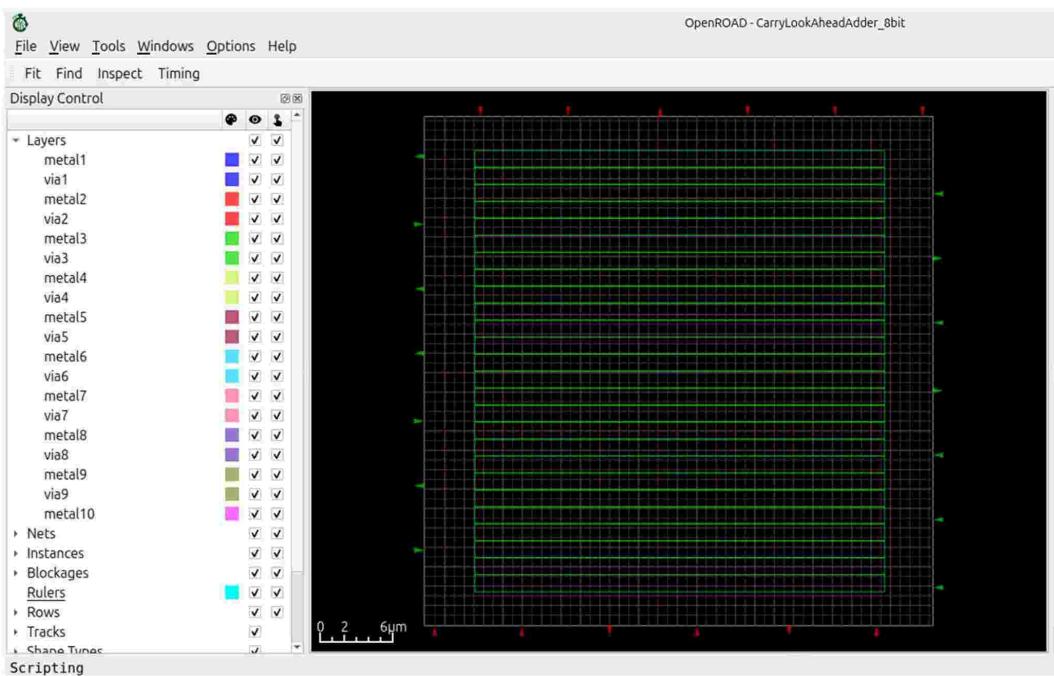


Fig 3.3.4 IO\_Placement\_Random Command Output Window

Step 29: Next step is macro-placement which can be done by using command,

```
# Macro Placement
if {[have_macros]} {
    global_placement -density $global_place_density
    macro_placement -halo $macro_place_halo -channel $macro_place_channel
}
```

Step 30: Now our next target is to create tapcell insertion by using following command,

```
# Tapcell insertion
eval tapcell $tapcell_args
```

This will show some significant changes in output window, which shown in Fig 3.3.5

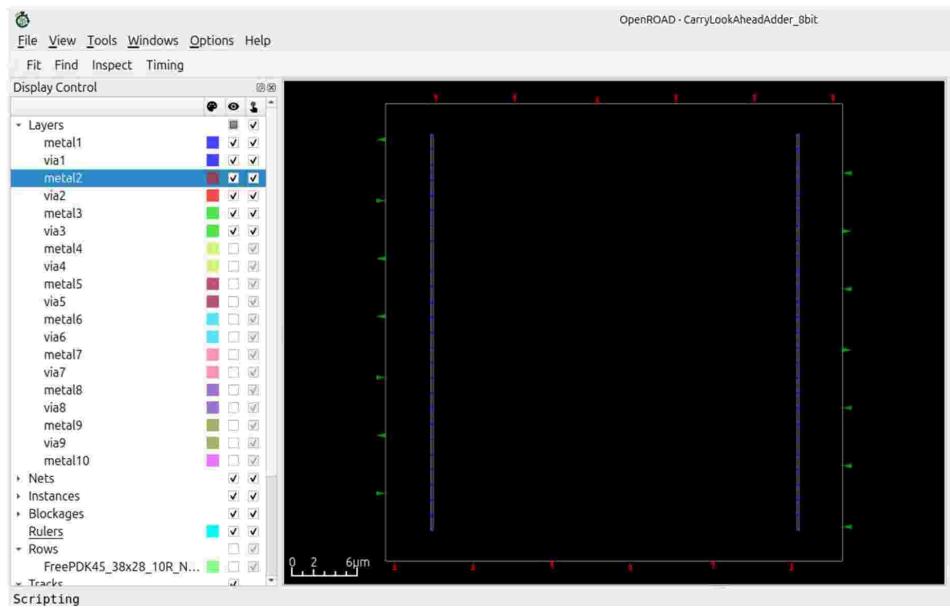


Fig 3.3.5 Tapcell Insertion Command Output Window

Step 31: Insertion of power distribution network using following command,

**# Power distribution network insertion**

**source \$pdn\_cfg**

**pdngen**

This command renders some significant changes to output window,

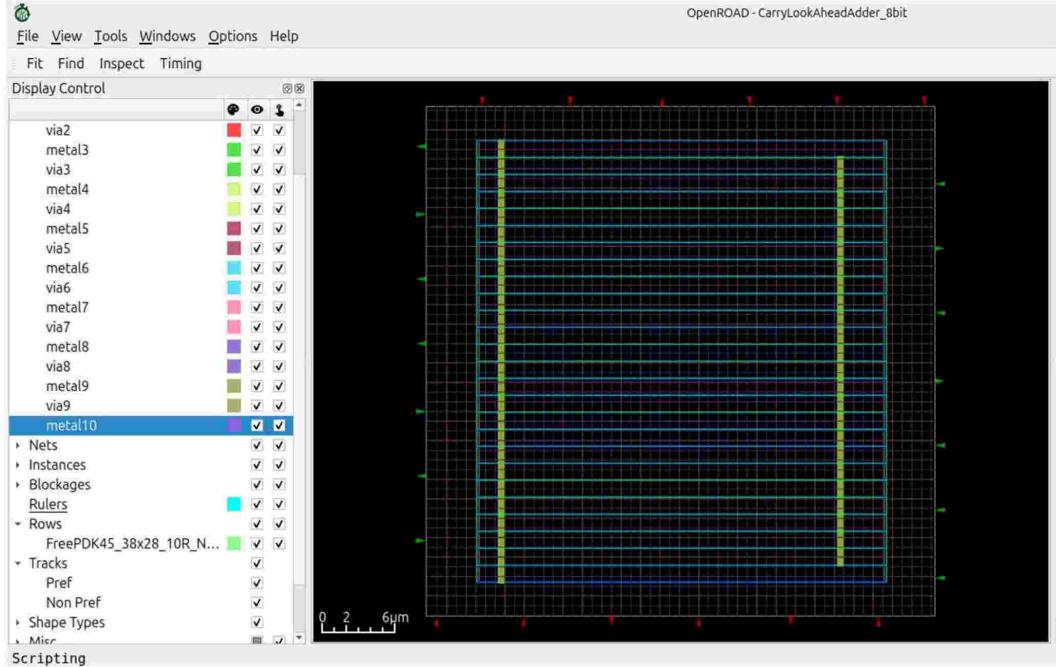


Fig 3.3.6 PDN Command Output Window

Step 32:The next step is of global placement of different parts layers interlinks, we can see some red instances in the chip design area by using following commands for global placement,

```
# Global placement
foreach layer_adjustment $global_routing_layer_adjustments {
    lassign $layer_adjustment layer adjustment
    set_global_routing_layer_adjustment $layer $adjustment
    set_routing_layers -signal $global_routing_layers \
        -clock $global_routing_clock_layers
    set_macro_extension 2
    global_placement -routability_driven -density $global_place_density \
        -pad_left $global_place_pad -pad_right $global_place_pad
```

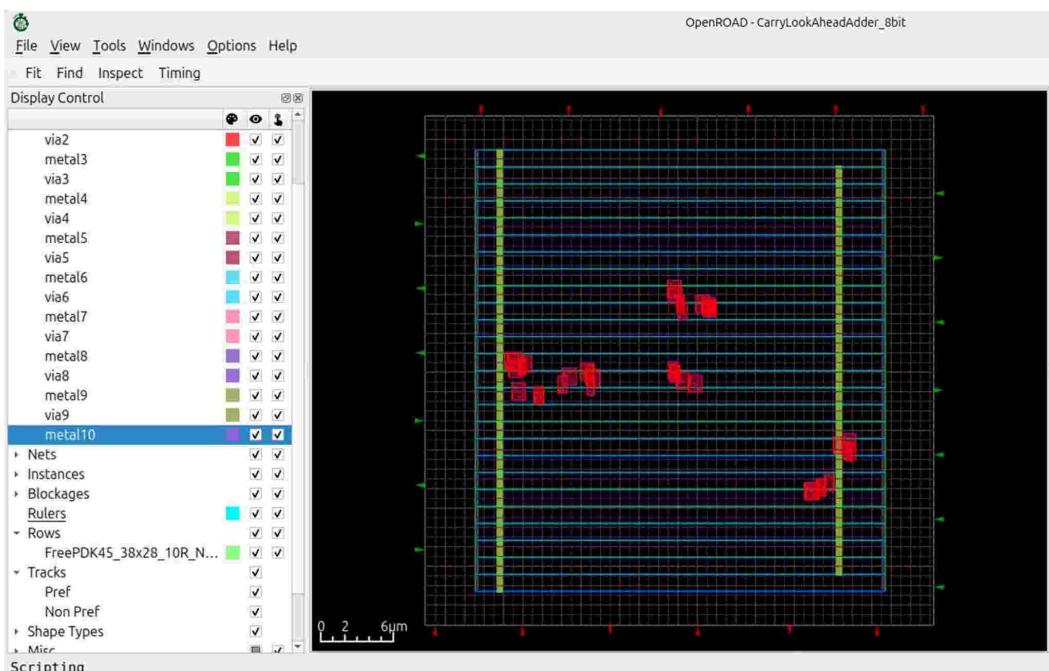


Fig 3.3.7 Global Placement Command Output Window

Step 33:Now we will organize the Input and Output Placements, by using following commands, # **IO Placement**

```
place_pins -hor_layers $io_placer_hor_layer -ver_layers $io_placer_ver_layer
```

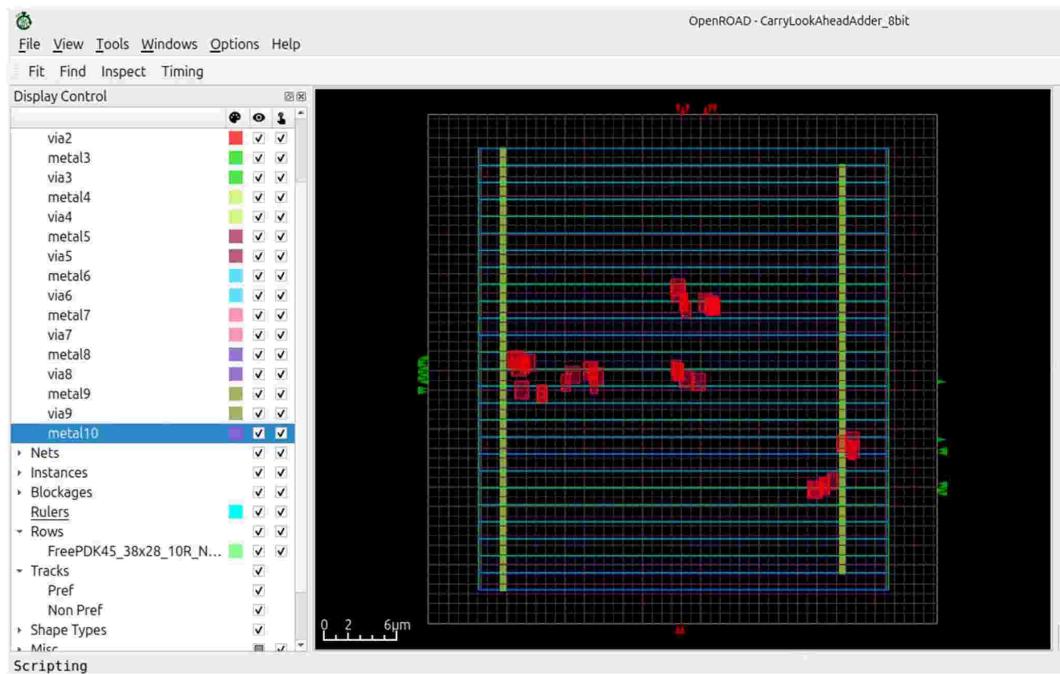


Fig 3.3.8 IO Placement Command Output Window

Step 34: Now we must set a checkpoint by using following command,

```
# checkpoint
set_global_place_db [make_result_file ${design}_${platform}_global_place.db]
write_db $global_place_db
```

Step 35: Now we have to optimize and repair the design by maximum of slew, capacitance and fanout violations and normalizing the slew by following commands,

```
# Repair max slew/cap/fanout violations and normalize slews
source $layer_rc_file
set_wire_rc -signal -layer $wire_rc_layer
set_wire_rc -clock -layer $wire_rc_layer_clk
set_dont_use $dont_use
estimate_parasitics -placement
repair_design -slew_margin $slew_margin -cap_margin $cap_margin
repair_tie_fanout -separation $tie_separation $tie_lo_port
repair_tie_fanout -separation $tie_separation $tie_hi_port
set_placement_padding -global -left $detail_place_pad -right $detail_place_pad
detailed_placement
# post resize timing report (ideal clocks)
report_worst_slack -min -digits 3
report_worst_slack -max -digits 3
report_tns -digits 3
# Check slew repair
report_check_types -max_slew -max_capacitance -max_fanout -violators
utl::metric "RSZ::repair_design_buffer_count"
[rsz::repair_design_buffer_count]
utl::metric "RSZ::max_slew_slack" [expr ${sta::max_slew_check_slack_limit} *
```

```

100]
utl::metric "RSZ::max_fanout_slack" [expr
[sta::max_fanout_check_slack_limit] * 100]
utl::metric "RSZ::max_capacitance_slack" [expr
[sta::max_capacitance_check_slack_limit] * 100]

```

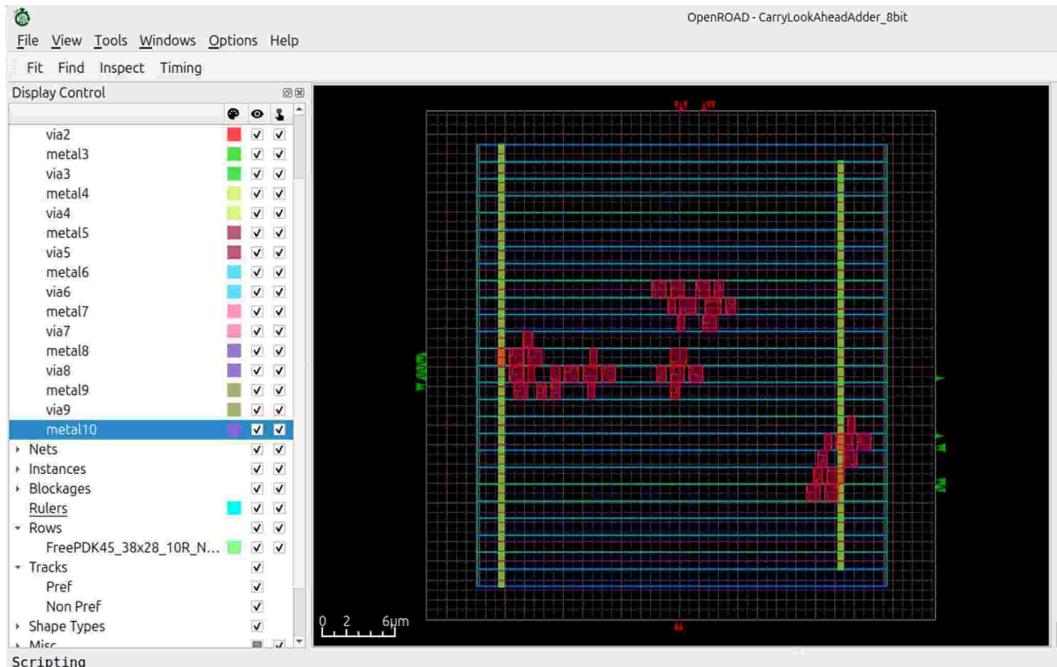


Fig 3.3.9 Repair Design Command Output Window

The console outputs and analysis we get at console window are,  
***Placement Analysis***

```

total displacement      47.8 u
average displacement    0.5 u
max displacement        2.3 u
original HPWL          420.3 u
legalized HPWL          490.7 u
delta HPWL              17 %
worst slack 0.202
worst slack -0.042
tns -0.070

```

Step 36: Now next part is also important as we do CTS in next part, using following command group,

```

# Clock Tree Synthesis
# Clone clock tree inverters next to register loads
# so cts does not try to buffer the inverted clocks.
repair_clock_inverters

```

```

clock_tree_synthesis -root_buf $cts_buffer -buf_list $cts_buffer \
-sink_clustering_enable \
-sink_clustering_max_diameter $cts_cluster_diameter
# CTS leaves a long wire from the pad to the clock tree root.
repair_clock_nets
# place clock buffers
detailed_placement
# checkpoint
set cts_db [make_result_file ${design}_${platform}_cts.db]
write_db $cts_db

```

This will set buffers and clock buffers and give output of no. of valid clock nets according to design, The most important parameter out by this commands is Using max wire length which is 693 um in our design.

#### Placement Analysis

```

-----
total displacement      0.0 u
average displacement   0.0 u
max displacement       0.0 u
original HPWL         490.7 u
legalized HPWL        490.7 u
delta HPWL            0 %

```

Step 37: Now setup and hold timing repair for the chip design in another part of CTS, by using following commands,

```

# Setup/hold timing repair
set_propagated_clock [all_clocks]
# Global routing is fast enough for the flow regressions.
# It is NOT FAST ENOUGH FOR PRODUCTION USE.
set repair_timing_use_grt_parasitics 0
if { $repair_timing_use_grt_parasitics } {
# Global route for parasitics - no guide file required
global_route -congestion_iterations 100
estimate_parasitics -global_routing
} else {
estimate_parasitics -placement
}
repair_timing -skip_gate_cloning
# Post timing repair.
report_worst_slack -min -digits 3
report_worst_slack -max -digits 3
report_tns -digits 3
report_check_types -max_slew -max_capacitance -max_fanout -violators -
digits 3
utl::metric "RSZ::worst_slack_min" [sta::worst_slack -min]
utl::metric "RSZ::worst_slack_max" [sta::worst_slack -max]
utl::metric "RSZ::tns_max" [sta::total_negative_slack -max]
utl::metric "RSZ::hold_buffer_count" [rsz::hold_buffer_count]

```

Those commands will give rendered output for virtual clock core\_clock cannot be

propagated which may differ design by design, and an Placement Analysis as shown in down outputs,

#### ***Placement Analysis***

---

<b><i>total displacement</i></b>	<b><i>12.4 u</i></b>
<b><i>average displacement</i></b>	<b><i>0.1 u</i></b>
<b><i>max displacement</i></b>	<b><i>2.6 u</i></b>
<b><i>original HPWL</i></b>	<b><i>495.3 u</i></b>
<b><i>legalized HPWL</i></b>	<b><i>509.7 u</i></b>
<b><i>delta HPWL</i></b>	<b><i>3 %</i></b>

Step 38: Let us have now detailed placement of our design using following commands,

```
# Detailed Placement
detailed_placement
# Capture utilization before fillers make it 100%
utl::metric "DPL::utilization" [format %.1f [expr [rsz::utilization] * 100]]
utl::metric "DPL::design_area" [sta::format_area [rsz::design_area] 0]
# checkpoint
set dpl_db [make_result_file ${design}_${platform}_dpl.db]
write_db $dpl_db
set verilog_file [make_result_file ${design}_${platform}.v]
write_verilog $verilog_file
```

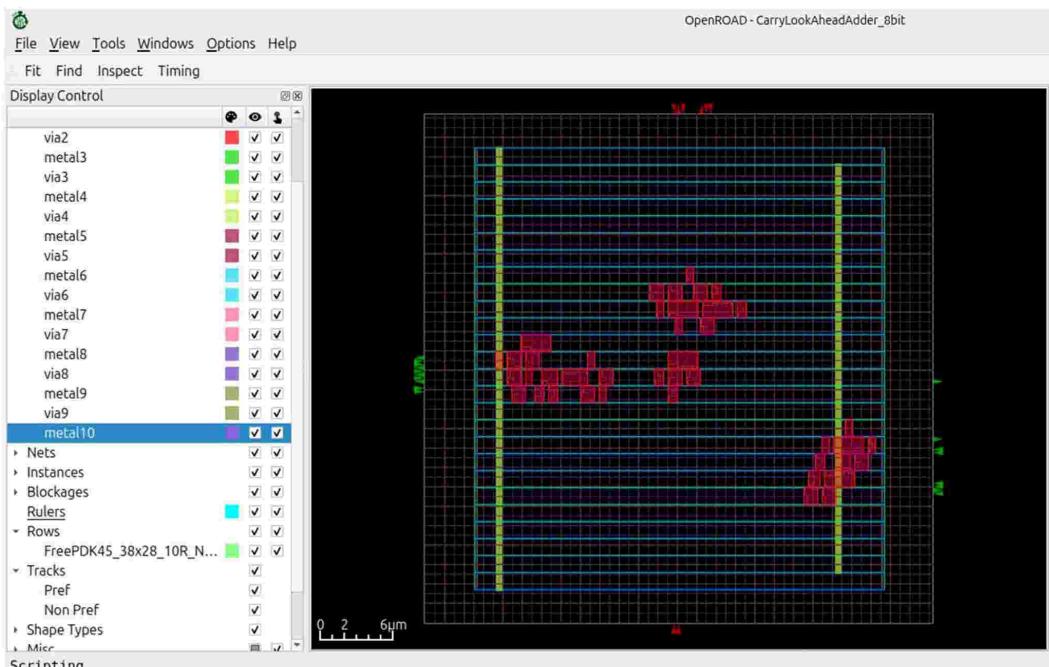


Fig 3.3.10 Detailed Placement Command Window Output

The console will give some outputs parameters of design given as also enlists the default vias layer by layer vias,

Step 39: After all this rendering we now do global routing by using following commands,

```
# Global routing
pin_access -bottom_routing_layer $min_routing_layer \
            -top_routing_layer $max_routing_layer
set route_guide [make_result_file ${design}_${platform}.route_guide]
global_route -guide_file $route_guide \
             -congestion_iterations 100
set verilog_file [make_result_file ${design}_${platform}.v]
write_verilog -remove_cells $filler_cells $verilog_file
```

This command will give some parameters such as,

**Reading tech and libs**

**Units:** 2000

**Number of layers:** 21

**Number of macros:** 135

**Number of vias:** 30

**Number of viarulegen:** 19

**Reading design.**

**Design:** CarryLookAheadAdder\_8bit

**Die area:** (0 0) (84000 84000)

**Number of track patterns:** 20

**Number of DEF vias:** 0

**Number of components:** 94

**Number of terminals:** 26

**Number of snets:** 2

**Number of nets:** 59

**And list of vias different metal vias,**

This will be also part of global routing report

**Start pin access.**

**Complete 57 pins.**

**Complete 17 unique inst patterns.**

**Complete 42 groups.**

**#scanned instances = 94**

**#unique instances = 21**

**#stdCellGenAp = 474**

**#stdCellValidPlanarAp = 0**

**#stdCellValidViaAp = 335**

**#stdCellPinNoAp = 0**

**#stdCellPinCnt = 134**

**#instTermValidViaApCnt = 0**

**#macroGenAp = 0**

**#macroValidPlanarAp = 0**

**#macroValidViaAp = 0**

**#macroNoAp = 0**

**Complete pin access.**

Step 40: Now we will repair any possible defects of Antenna by using following commands,

```
# Antenna repair
repair_antennas -iterations 5
check_antennas
utl::metric "GRT::ANT::errors" [ant::antennaViolationCount]
```

This will be give output of any net and pin violations, and give output as  
**Found 0 net violations.**

**Found 0 pin violations.**

Step 41: Now the next part is filler placement in design by using following commands,

```
# Filler placement
filler_placement $filler_cells
check_placement -verbose
# checkpoint
set fill_db [make_result_file ${design}_ ${platform}_fill.db]
write_db $fill_db
```

There will be significant changes in output window of design,

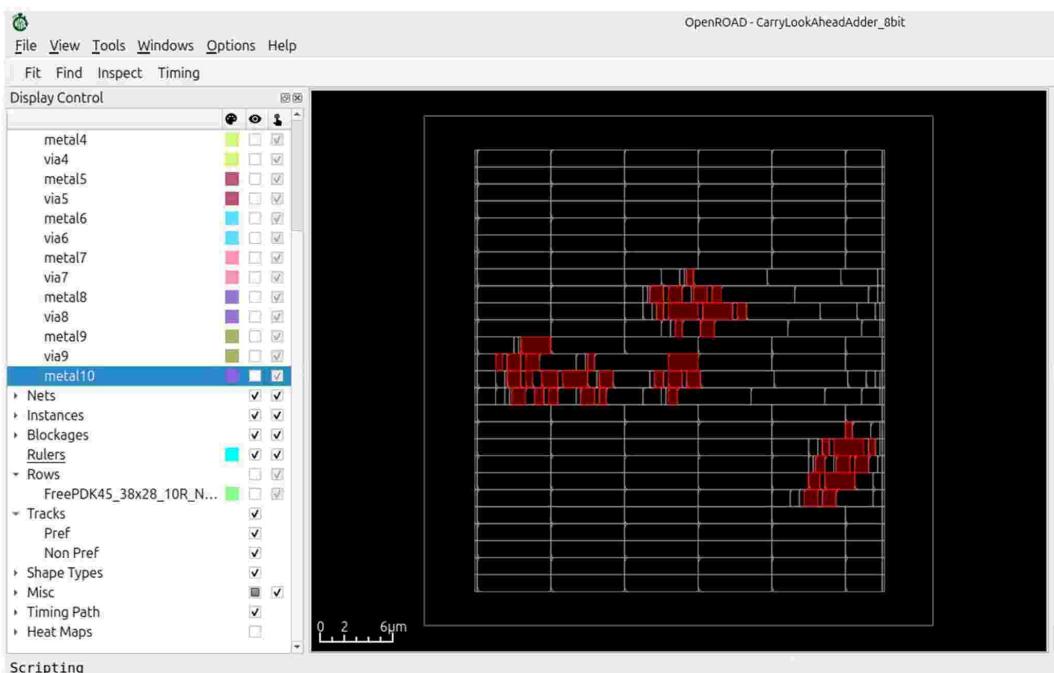


Fig 3.3.11 Filler Placement Command Window Output

Step 42: Now we will be doing detailed routing of our design using following commands,

```
# Detailed routing
# Run pin access again after inserting diodes and moving cells
pin_access -bottom_routing_layer $min_routing_layer \
-top_routing_layer $max_routing_layer
```

```

set_thread_count [exec getconf_NPROCESSORS_ONLN]
detailed_route
-output_drc [make_result_file "${design}_${platform}_route_drc.rpt"] \
-output_maze [make_result_file "${design}_${platform}_maze.log"] \
-no_pin_access \
-save_guide_updates \
-bottom_routing_layer $min_routing_layer \
-top_routing_layer $max_routing_layer \
-verbose 0
write_guides [make_result_file "${design}_${platform}_output_guide.mod"]
set drv_count [detailed_route_num_drvs]
utl::metric "DRT::drv" $drv_count
check_antennas
utl::metric "DRT::ANT::errors" [ant::antennaViolationCount]
set routed_db [make_result_file ${design}_${platform}_route.db]
write_db $routed_db
set routed_def [make_result_file ${design}_${platform}_route.def]
write_def $routed_def

```

This commands will run at instances to provide different output checks and only some parameters which required internally to display design

Step 43: This will help in extraction of SPEF

```

# Extraction
if { $rcx_rules_file != "" } {
    define_process_corner -ext_model_index 0 X
    extract_parasitics -ext_model_file $rcx_rules_file
    set spef_file [make_result_file ${design}_${platform}.spef]
    write_spef $spef_file
    read_spef $spef_file
} else {
    # Use global routing based parasitics inlieu of rc extraction
    estimate_parasitics -global_routing
}

```

These commands will check the give some error checks and final SPEF file for detailed information of interconnections between different components and gates, pins to the chip and design.

Step 44: To get the final report of the design and final design we can use the following commands,

```

# Final Report
report_checks -path_delay min_max -format full_clock_expanded \
-fields {input_pin slew capacitance} -digits 3
report_worst_slack -min -digits 3
report_worst_slack -max -digits 3
report_tns -digits 3
report_check_types -max_slew -max_capacitance -max_fanout -violators - \
digits 3

```

```

report_clock_skew -digits 3
report_power -corner $power_corner
report_floating_nets -verbose
report_design_area
utl::metric "DRT::worst_slack_min" [sta::worst_slack -min]
utl::metric "DRT::worst_slack_max" [sta::worst_slack -max]
utl::metric "DRT::tns_max" [sta::total_negative_slack -max]
utl::metric "DRT::clock_skew" [expr abs([sta::worst_clock_skew -setup])]
# slew/cap/fanout slack/limit
utl::metric "DRT::max_slew_slack" [expr [sta::max_slew_check_slack_limit]
* 100]
utl::metric "DRT::max_fanout_slack" [expr
[sta::max_fanout_check_slack_limit] * 100]
utl::metric "DRT::max_capacitance_slack" [expr
[sta::max_capacitance_check_slack_limit] * 100];
# report clock period as a metric for updating limits
utl::metric "DRT::clock_period" [get_property [lindex [all_clocks] 0] period]
# not really useful without pad locations
#set_pdnsim_net_voltage -net $vdd_net_name -voltage $vdd_voltage
#analyze_power_grid -net $vdd_net_name

```

The final report can be found in results folder of test for all detailed information and parameters if the designed chip, This is the final GDSII layout given in figure below,

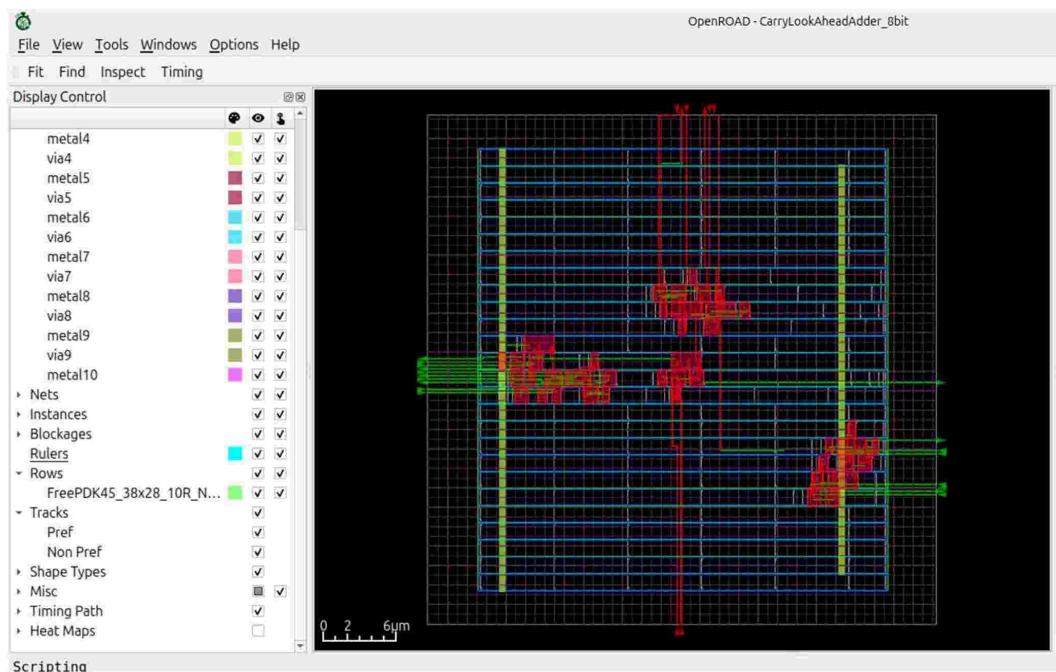


Fig 3.3.12 The Final CarryLookAheadAdder\_8bit Design Output

### 3.4 SOME DESIGN IMPLEMENS

I have designed some designs implemented on basis of the PDK nangate45 which uses 45nm technology.

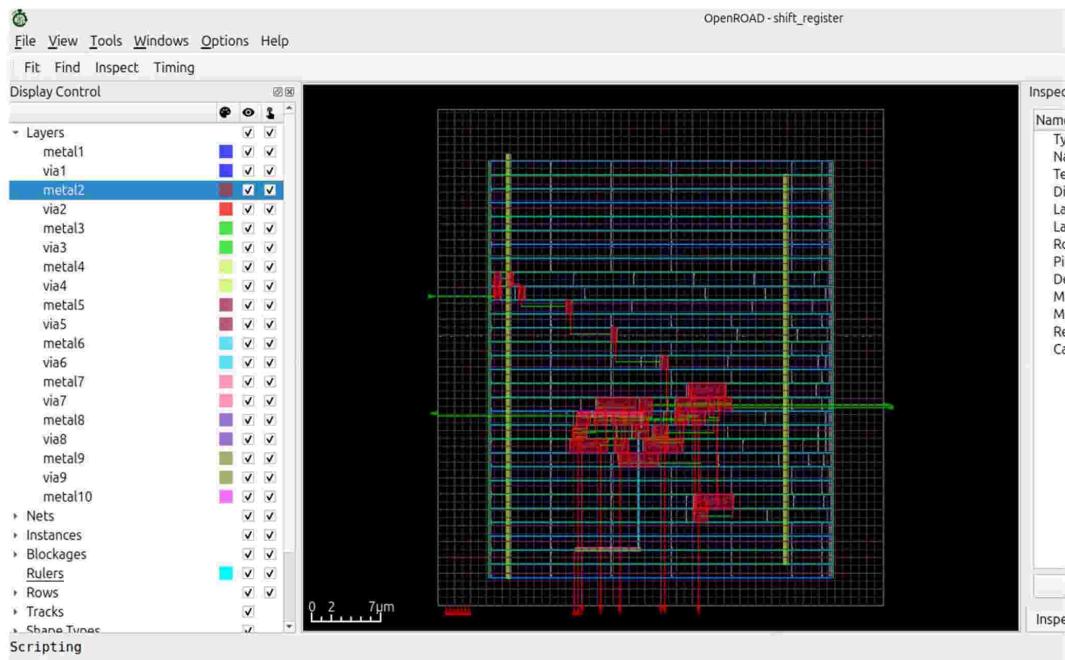


Fig 3.4.1 Shift\_Register Final GDSII Layout Design

The CSA design implemented using nangate45 standard cell library, with set die\_area {0 0 60 60}, set core\_area {5 2 56 60}, max wire length of 693 um.

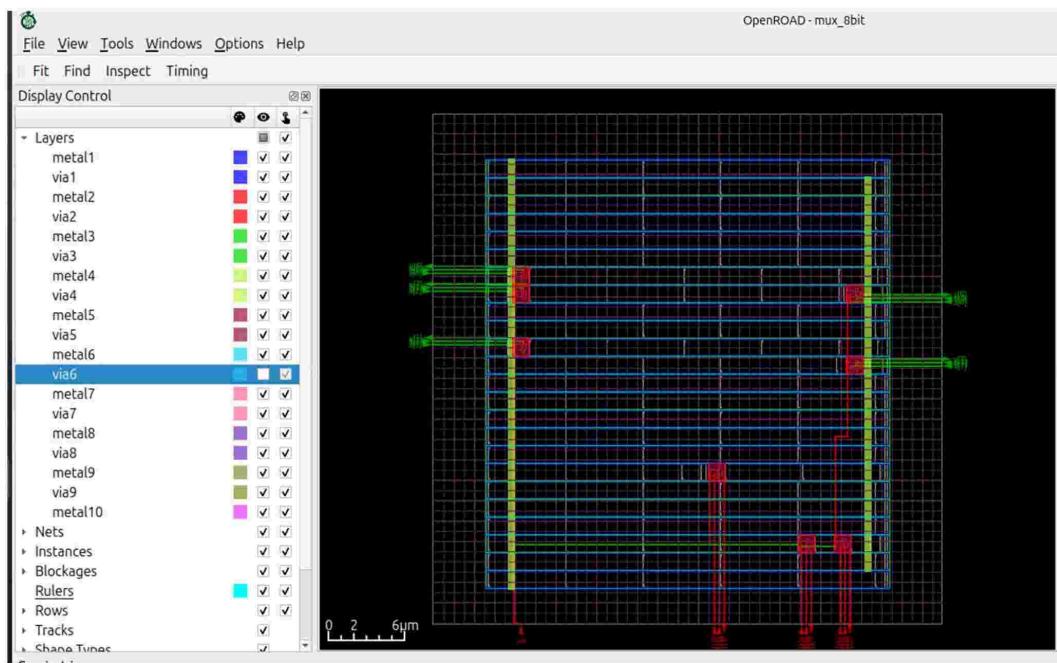


Fig 3.4.2 mux\_8bits Final GDSII Layout Design

The RCA design implemented using nangate45 standard cell library, with set die\_area {0 0 40 40}, set core\_area {4 2 36 37}, max wire length of 693 um.

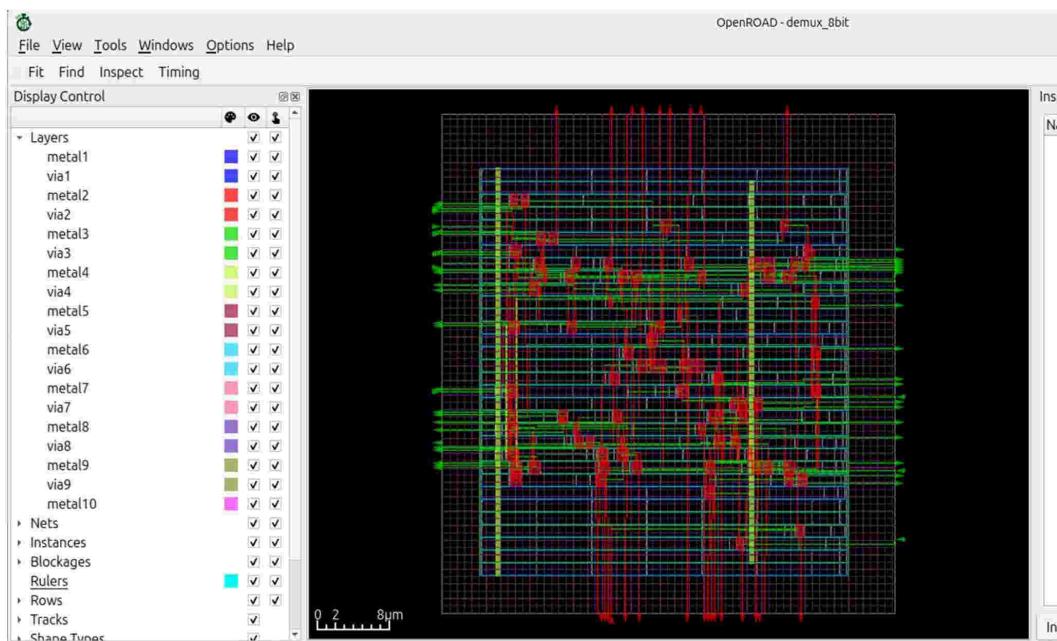


Fig 3.4.3 demux\_8bits Final GDSII Layout Design

The 8-bit Multiplier design implemented using nangate45 standard cell library, with set die\_area {0 0 50 55}, set core\_area {4 3 45 50}, max wire length of 693 um.

## CHAPTER 4: SUMMARY

Let me summarize the activities I done during my internship. Initially I was doing design implementations on Xilinx and trying to install ORFS. I had learned about the different kind of advanced adders used in computer architecture also, learned about the multipliers which applied as DSP, and convolutors for Machine Learning and Deep Learning Model architectures. I had explored about the lab facilities available to students and researchers in the SVNIT. The installation ORFS was not easy, I have spent over a week to just get that ORFS on my system. And after getting the software ORFS I explored about how to use it, I got familiar to code hub which is known as github. Before all this I learned how to use ubuntu basics as that software is a opensource hence not available in Windows based system. The ORFS supports many other PDKs also which make its more useful for initial research and design implementations.

## References/ Bibliography

As per the guidelines and the references given by GTU, Ahmedabad. I have tried to keep this thesis report / Internship Report as sole creator and writer me, although 100% cannot be done by me hence I have taken references of designs and some terms and important images and parts from the web, knowingly or some others may show in plagiarism report, Some of references used by me knowingly are listed below,

- [Invent Logics - Shop Now for Xilinx FPGA development boards \(allaboutfpga.com\)](#)
- [The OpenROAD Project · GitHub](#)
- [Online Collaborative Whiteboard | Sketchboard](#)
- [VLSI Physical Design with Timing Analysis - Course \(nptel.ac.in\)](#)
- [OpenROAD Flow Scripts Tutorial — OpenROAD Flow documentation \(openroad-flow-scripts.readthedocs.io\)](#)
- [OpenLane using Codespaces : RTL-to-GDSII flow. - Part-2 \(youtube.com\)](#)
- [https://www.youtube.com/watch?v=\\_AXknRBk4QI](https://www.youtube.com/watch?v=_AXknRBk4QI)
- [OpenROAD and efabless OpenLane at the CHIPKIT tutorial, ISCA-2020 \(youtube.com\)](#)
- And there my be some other similar references can be listed in Plagiarism report which are unknowingly references.

## STUDENT'S DAILY DIARY/ LOG

Name of student: Sahu Arabinda K.

Date	Day	Name of completed Task	Work of the day	Sign of the Industry supervisor
29 - 06 - 24	Saturday	Installation of xilinx & use of xilinx on a system.	On the day I have given task to install xilinx vivado design suite on my system & learn how to use xilinx to do logic simulation & abstract to RTL design of circuit.	
30 - 06 - 24	Sunday	Holiday	-	-
01 - 07 - 24	Monday	Ripple Carry Adder	Learning about the RCA logic of binary addition, its logical circuit building & realisation. And done RTL from verilog / VHDL on xilinx ISE.	
02 - 07 - 24	Tuesday	Carry Look Ahead Adder	Learning about the CLA logic of binary addition of n-bit width, its logical circuit realisation and RTL from verilog / VHDL on xilinx ISE.	
03 - 07 - 24	Wednesday	Carry Save Adder	Learning about the CSA logic of binary addition of n-bit width, its logical circuit realisation and RTL from verilog / VHDL on xilinx ISE.	

## STUDENT'S DAILY DIARY/ LOG

Name of student: Sahu Arambinda K.

Date	Day	Name of completed Task	Work of the day	Sign of the Industry supervisor
21-07-2010	Thursday	Fast - Array Multipliers	Learning about the fast multiplier logic of upto 8 bit width its logical circuit realisation and RTL from verilog /VHDL on xilinx ISE	
22-07-2010	Friday	Booth Multiplier	Learning about the Booth algorithm of nbit binary multiplication and its logical circuit realisation. And done RTL from verilog /VHDL on xilinx ISE.	
03-07-2010	Saturday	Holiday	-	-
04-07-2010	Sunday	Holiday	-	-
05-07-2010	Monday	Installation of Openroad flow scripts & openroad Tool .	Installing the ORFS , before that making system dual boot as ORFS supported in Unix only. Then installing the ORFS & all tools related to open Road Projectflow scripts.	

## STUDENT'S DAILY DIARY/ LOG

Name of student: Sahu Arabinela K.

Date	Day	Name of completed Task	Work of the day	Sign of the Industry supervisor
12-07-09	Tuesday	Learning & Exploring about Tools in ORFS	Learning about tools such as Yosys Synthesizer, STA pre and post by OpenSTA, Migration tool, Magic VLSI DRC, Lvs checker tools & Learn about the flow of Physical design	
13-07-10	Wednesday	Step by Step Implementation of CLA RTL-to-GDS	Step by step process mentioned in report, following those steps. Implemented CLA from Verilog code to RTL & then RTL to GDS in between many processes. Using ORFS & mangate us PDK.	
14-07-11	Thursday	Other Design Implementation in ORFS	On this day implemented various other designs such as multiplex 4:8, demux 8:1 & shift register of 8 bit width. using Mangate us PDK.	
15-07-12	Friday	Presentation & Report Submission.	Presentation & Report Submission for the evaluation of the Internship.	



**GUJARAT TECHNOLOGICAL UNIVERSITY**  
**(Established under Gujarat Act No. 20 of 2007)**

ગુજરાત ટેકનોલોજીકલ યુનિવર્સિટી  
 (ગુજરાત અધિનિયમ ક્રમાંક: ૨૦/૨૦૦૭ દ્વારા સ્થાપિત)

## Annexure I

Enrollment no:

210230111008**STUDENT'S WEEKLY RECORD OF INTERNSHIP**NAME OF STUDENT: SAHU ARABINDADIARY OF THE WEEK: Dt: 29-06-24 TO 05-07-24DEPARTMENT: E. C. SEM: 7<sup>th</sup>NAME OF THE ORGANISATION: SUNIT, SuratNAME OF THE PLANT/SECTION/DEPARTMENT: Electronics Engineering DepartmentNAME OF OFFICER INCHARGE OF THE PLANT/SECTION/DEPARTMENT: Prof. P. D. Engnani**DESCRIPTION OF THE WORK DONE IN BRIEF**

During week-I I am assigned work related to abstract level of logical digital circuits to the RTL of the circuits.

During this week I learned about different kind of advanced adders & multipliers used in COA, done some simulations on Xilinx related to different Digital circuits, done their timing analysis on paper and go through the process of Synthesizing verilog / VHDL code to RTL only.



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 (ગુજરાત અધિનિયમ ક્રમાંક ૨૦/૨૦૦૭ દ્વારા સ્થાપિત)

TOTAL HOURS: 36 hours

  
 SIGNATURE OF STUDENT

- ⦿ The above entries are correct and the grading of work done by Trainee is EXCELLENT / VERY GOOD / GOOD / FAIR / BELOW AVERAGE / POOR

  
 Signature of Faculty Mentor

  
 Signature of officer-in-charge  
 of Dept. / Section / Plant

Date: 2

Date:

- ✿ Grading of Work, for trainee may be given depending upon your judgement about his Punctuality, Regularity, Sincerity, Interest taken, Work done etc.

WPR13



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**SUPPLEMENTARY NOTES**  
(add additional sheets if required)



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## Annexure I

Enrollment no:

210230111008**STUDENT'S WEEKLY RECORD OF INTERNSHIP**NAME OF STUDENT: SAHU ARABINDA KITALASHDIARY OF THE WEEK: Dt: 06-07-24 TO 12-07-24DEPARTMENT: E.C. SEM: 7thNAME OF THE ORGANISATION: SUNIT, SURATNAME OF THE PLANT/SECTION/DEPARTMENT: Electronics Engineering DepartmentNAME OF OFFICER INCHARGE OF THE PLANT/SECTION/DEPARTMENT: Prof. J. Engn.**DESCRIPTION OF THE WORK DONE IN BRIEF**

During week-2 I was instructed to install ORFS & its tools in my system to do RTL to GDS of physical Design flow. In this week I learned about the physical design flow - the IC designing & implemented some designs such as CLA, shift registers, mux 1:8 & Demux 8:1 mentioned in report & some small designs just to understand the ORFS design tool.

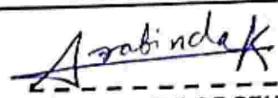
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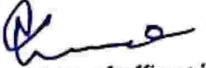
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(ગાજરાત અધિનિયમ ક્રમાંક: ૨૦/૨૦૦૭ દારા સ્થાપિત)

TOTAL HOURS: 3. hours

  
SIGNATURE OF STUDENT

- The above entries are correct and the grading of work done by Trainee is  
EXCELLENT / VERY GOOD / GOOD / FAIR / BELOW AVERAGE / POOR

  
Signature of Faculty Mentor

  
Signature of officer-in-charge  
of Dept. / Section / Plant

Date:

Date:

- ★ Grading of Work, for trainee may be given depending upon your judgement about  
his Punctuality, Regularity, Sincerity, Interest taken, Work done etc.



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**SUPPLEMENTARY NOTES**  
(add additional sheets if required)



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**Annexure 2**

**Feedback Form by Industry expert**

Student Name: Satv Arabinda Kailash

Date: 15 - 07 - 2024

Work Supervisor: Prof P. J. Engrew

Title:

Company/Organization: Sardar Vallabhbhai National Institute of Technology

Enrollment No: 210230111 008

Internship Address: SVNIT, Electronics department, Ichchhanath, Keval Chowk, Surat

Dates of Internship: From 29 - 06 - 2024 to 02 - 07 - 24

Please evaluate your intern by indicating the frequency with which you observed the following behaviors:

Parameters	Needs improvement	Satisfactory	Good	Excellent
Shows interest in work and his/her initiatives				✓
Produces high quality work and accepts responsibility	.			✓
Uses technical knowledge and expertise				✓
Analyzes problems effectively			✓	
Communicates well and writes effectively				✓

Overall performance of student intern: (Needs improvement/ Satisfactory/Good/Excellent):

Excellent

Additional comments, if any:

Signature of Industry person with name and Stamp:

Signature of the Faculty Mentor



### Evaluation Rubrics

**List of Documents to be prepared for Submission:**

- Detail report duly signed and approved by the internal/external mentor
- Presentation softcopy approved by the internal/external mentor
- CD – Scan copy of report and presentation

Student Details											
Enrollment Number	2	1	0	2	3	0	1	1	0	0	8
Student Name	SAHU ARABINDA KAILASH										
Branch	ELECTRONICS & COMMUNICATION										
Code and Name of the Institute	023 - Dr. S. & S.S. CHANDHY GOVERNMENT ENGINEERING COLLEGE, SURAT										
Mentor Details	<p>Name: Dr. Pinalkumar J. Engineer Designation: Mobile No: 9426148051</p>										
Mode of Internship Carried Out	Online / Offline										
Title of the Project/ Internship carried out	VLSI Physical Design										
Nature of Work Carried Out	<p>Small fabrication / experimental results/ simulations/ Application development / Design and / or Analysis of System(s) etc... Other please Specify _____</p>										

### Evaluation Rubrics

Enrollment No: 210230111008

Branch: E. C.

Name of the Students: SAMU ARABINDA KAZLASH

Date of Evaluation: \_\_\_\_\_

**Internal Evaluation - 20 Marks PA(I)**  
**(To be carried out by the mentor in consultation with Industry)**  
**Minimum Passing Marks: 10**

Parameter	Excellent	Very Good	Good	Not up the level of Satisfaction	Obtained Marks
Mark range	10	09-08	07-05	Below 5	
Student regularity during the Internship period and proactiveness/responsiveness towards the given tasks <b>10 marks</b>	10				10
Quality of the prepared report <b>10 marks</b>	10				10
<b>Total Marks Obtained Out of 20 PA(I)</b>					<b>20</b>

**External Evaluation - 80 Marks ESE(V)**  
**Minimum Passing Marks: 40**

Parameter	Excellent	Very Good	Good	Average	Not up the level of Satisfaction	Obtained Marks
Mark range	20-17	16-15	14-12	11-10	Below 10	
Adequacy and Quality of the Work carried Out (20 Marks)						
Tools and Techniques Used and to achieve the objectives of the work (20 Marks)						
Work Plan and Execution and Outcome achieved (20 Marks)						
Quality of the report and presentation Skill (20 Marks)						
<b>Total Marks Obtained Out of 80 ESE(V)</b>						

External Examiner Name: P. J Engineer

External Examiner Name: \_\_\_\_\_

Signature: [Signature]

Signature: \_\_\_\_\_

99% 1% 0%  
Unique Content Plagiarized Content Paraphrased Plagia

### Content Checked For Plagiarism:

VLSI Physical Design Offline Internship Report Team ID: 587579 Report Submitted by SAHU ARABINDA KAILASH EN. NO: - 210230111008 In partial fulfilment for the award if the degree of Bachelor of Engineering in Electronics and Communication Engineering Dr.S. & S.S. Ghandhy Government Engineering College, Surat -5651423241043097450 Gujarat Technological University, Ahmedabad June-July 2024 1042386250 Dr.S. Ghandhy Government Engineering College, Surat Near Vanita Vishram Swimming Pool, Majura Gate, Ring Road, Surat -395001 Certificate Date: This is to certify that the project report submitted along with the project entitled VLSI Physical Design has been carried out by Sahu Arabinda Kailash under my guidance in partial fulfillment for the degree of Bachelor of Engineering in Electronics and Communication Engineering, 7th Semester of Gujarat Technological University, Ahmedabad during the academic year 2024-25. Prof. P. V. Pithadiya Prof. T. P. Dave (Internal Guide)(Head of Department) Letter head certificate signed by Internship mentor DECLARATION OF ORIGINALITY I hereby declare that the Internship report submitted along with the Internship entitled VLSI Physical design submitted in partial fulfillment for the degree of Bachelor of Engineering in Electronics and Communication engineering to Gujarat Technological University, Ahmedabad, is a bona fide record of original project work carried out by me at SVNIT under supervision of Dr.

Pinalkumar J. Engineer and that no part of this report has been directly copied from any student's reports or taken from any other source, without providing due reference. Date: Place: Surat SAHU ARABINDA KAILASH .. 210230111008 ACKNOWLEDGMENT This is the place to admit that while there appears only author on the cover, this work just as any other, is a product of the interaction with and support during our internship work, among them, first I express my gratitude to my guides Dr. Engineer & Prof. Dharmesh J. Patel for their affection throughout guidance, advice, and encouragement. Special thanks to my college for giving me the invaluable knowledge. Also, I interacted with some other students having their study and research there for guidance of software installation, I am grateful to them also for providing us guidance. Above all I am thankful to almighty God for everything. SAHU ARABINDA KAILASH Table of Contents LIST OF FIGURES I LIST OF TABLES III LIST OF ABBREVIATIONS IV ABSTRACT VI CHAPTER 1: INTRODUCTION 1 1.1 INTERNSHIP DESCRIPTION 1 1.

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ABBREVIATIONS Symbol Abbreviations SVNIT Sardar  
Vallabhbhai National Institute of Technology RTL Register  
Transfer Level GDS Graphic Design System IC Integrated  
Circuit VLSI Very Large-Scale Integration RCA Ripple Carry  
Adder CSA Carry Save Adder CLA Carry Look Ahead  
Adder E.C. Electronics and Communication nm nano meter  
FET Field Effect Transistor TSMC Taiwan Semiconductor  
Manufacturing Company GAA Gate-All-Around AI Artificial  
Intelligence ASIC Application Specific Integrated Circuit SoC  
System-on-Chip EDA Electronic Design Automation GTU  
Gujarat Technological University DGGEC Dr.S. & S.S.  
Ghandhy Government Engineering College ALU Arithmetic  
Logic Unit VHDL Very High-Speed Integrated Circuit  
Hardware Description Language LSB Least Significant Bit  
MSB Most Significant Bit DSP Digital Signal Processing EDA  
Electronic Design Automation CAD Computer-aided Design  
ORFS OpenROAD-flow-scripts SDC Synopsys Design  
Compiler GUI Graphic User Interface HDL Hardware  
Description Language WSL Windows Subsystem Linux  
VMBox Virtual Machine Box PDK ProcessDesign Kit CTS  
Clock Tree Synthesis BLIF Berkely Logic Interchange Format  
PDN Power Distribution Network SDC Synopsys Design  
Constraints SPEF Standard Parasitic Exchange Format um  
micro meter ABSTRACT The main objective of the internship  
program is to learn about the RTL to GDS Design flow of  
Digital circuits to form an IC. In the journey of this learning,  
we learned about advanced adders and multipliers and  
some other components. Also, during the program, we  
learned about open source tools and software related to  
ASIC designing process. The SVNIT has great environment  
and guidance for learnings. The internship is focused to the  
vlsi physical design flow in digital field. In duration of these  
internship, I learned a lot about Physical design aspect of  
VLSI and looking forward for VLSI ASIC design related  
works and projects. CHAPTER 1: INTRODUCTION In the E.C  
Engineering various Electronics devices are used such as  
resistor, transistors, diodes, and ICs. Among those devices  
IC are game changer technology. And all this possible due  
to semiconductors. Such as Silicon, graphene, etc. are  
generally used to form IC. The current IC technology  
window reached is of 5-3nm only. Further research to  
narrow the channel length of FETs is going on. The SoC such  
as Tensor G3 used in Google Pixel 8 Series, M3 used in  
latest MacBook, Exynos 2400 in Galaxy S24 series,  
Qualcomm's Snapdragon 5 gen 3 in Samsung galaxy S24  
ultra are one of the latest technology-based ASICs designed  
by foundries such as TSMC, GAA, and Samsung. Recently Nvidia became first  
company to research on IC based AI neural engines and  
render engines. All this discussion to ensure that our  
internship program for VLSI physical design flow is to learn  
about designing of ASICs. In most of Indian ASIC based  
companies are service based such as designing or testing  
and verification is carried out. I chose this topic of internship  
to explore about ASIC and RTL-to-GDS design flow.  
INTERNSHIP DESCRIPTION The Summer Internship of 2  
weeks is a part of GTU academics extra curriculum activity  
allowing students to get hands on experience before  
placement drives in campus. This report outlines the  
experiences and accomplishments during the internship  
period at the VLSI Research Lab in Electronics Engineering  
Department of SVNIT, under the mentorship and  
supervision of Dr. Engineer, Associate Professor at SVNIT.  
Duration of internship as mentioned by GTU Notification  
29th June 2024 to 12th July 2024. During this period in 11  
working days, the internship focused on the VLSI physical  
design flow in digital domain, providing exposure in  
implementing various digital circuits as RTL-to-GDS design  
such as RCA, CLA, CSA, Array Multipliers etc. VLSI technology  
is pivotal in the enhancement or advancement of modern  
electronics, enabling the creation of complex IC by  
combining thousands or millions of transistors onto a  
single chip. The physical design phase in VLSI involves  
conversion of a high-level abstract design into a detailed  
manufacturable layout.

This phase is crucial as it directly impacts the performance, power consumption, heat dissipation, and overall efficiency of IC. SCOPE AND OBJECTIVE OF INTERNSHIP 1.2.1 Objectives The primary objectives of internship were: To gain practical knowledge of the VLSI physical design flow. To implement and optimize physical designs for different types of digital circuits. To understand the tools and methodologies used in the VLSI design flow. 1.2.2 Scope of Internship During the internship the below mentioned tasks were undertaken: Implementation of different advanced adders and multiplier circuits in Xilinx tool for RTL and Simulation. Designing and Optimization of various integrated circuits. Use of open source EDA tools for layout design, verification, and optimization. This internship provided valuable insights into the intricacies of VLSI physical design, bridging the gap between theoretical knowledge and practical application. The experience gained has equipped me with the skills and understanding necessary to contribute effectively to the field of VLSI design.

CHAPTER 2: DESIGN ON XILINX

The initial stage of VLSI physical design flow is implementing the design module and verify the simulation output. For this we can create files such as Verilog file with ".v" extension, VHDL modules with ".vhd" file extension and ".tb" file extension for test bench. Those files are used to form the RTL, Schematics and Verification by simulation of logic with test vectors at Test bench. Apart from general digital circuits we learned in VLSI design subject and DSD subject of GTU syllabus I learned about multipliers and Advanced 8 bit and extensible digital circuit designs.

**ADVANCED ADDER DESIGNS**

In advanced adder architecture I learned about 3 kinds of adders used in forming ALUs and intermediate stage of multipliers used in ALU. The 3 kinds of Adder design I learned are 1) Ripple Carry Adder, 2) Carry Save Adder, 3) Carry Look Ahead Adder. Those adders have their specific application and use cases based on their design parameters such as size, delay, performance for n bits architecture and area occupied on chip etc. I have designed and implemented as per given instructions using VHDL programming and of 8 bits architecture for all these kinds. Let's see more about different adder designs in further sections.

**Ripple Carry Adder (RCA)**

A Ripple Carry Adder is digital binary adder circuit designed to two n-bit (n no. of bits in binary number). It is the extension to basic RCA concept, which scaled to handle any no of bits. The main building block of the RCA consists of Full Adders. As we know the Full Adder has three inputs as two operands and Carry input, and two outputs as Sum and Carry out. An n-bit RCA consists of chain of n Full adders (i.e. an 8-bit RCA consists of 8 Full Adder blocks).

The RCA provides a n-bit Sum output and Carry output based on provided 2 n-bit operands and carry in signal usually zero (0). A n-bit RCA does bit-wise addition of two operands using full adders, where the sum output of full adder will be summing output of corresponding bit and carry forwarded to next stage of full adder carry input. The term "Ripple" in RCA refers to the way of the carry propagation through the adders. The Carry out from the LSB adder ripples through the MSB of adder. This ripple propagation of carry causes delay proportional to the number of bits, making the adder slow for large width of bits. Whereas generally when we use an 8-bit RCA, and for addition of 16-bit operands we use RCA 2 times to save the area and provide performance. It is comparatively slower than CSA and CLA but design wise simplest among all other advanced n bit adders. Also, the hardware area is minimal as it comprises of series of full adders only. The general time delay of Full Adders are as follows Tsum for sum calculation typically involves XOR gate, and Tcarry for carry generation typically involves AND or OR gates.

Now, for the time delay calculation of n-bit RCA, consists of n full adders. Each stage carry output propagated after Tcarry delay hence n times Tcarry (i.e.  $n * Tcarry$ ). The sum output of corresponding bits available only after carry input of previous stage. The MSB calculated after n-1 bit's carry out generation, hence we can say that for an n-bit RCA the time delay is given by following equation  $T_{RCA} = n * (T_{carry} + T_{sum})$

2.1.1 Assuming  $T_{carry} = T_{sum}$ , for 8-bit RCA we get delay of 16-units time. 871763211454 Fig 2.1.1 8-Bit RCA RTL From Xilinx Design Implementation I have implemented 8-bit RCA during the internship also, implemented 4-bit design but showing results for 8-bit RCA only. Here I have used the generate function in VHDL so by which in RTL view we can see that there is only one full adder block is being shown. Fig 2.1.2 8-Bit RCA Simulation Output From Xilinx Design Implementation RCA is basically used in simple arithmetic units where speed isn't the primary concern, for learning and educational purposes due to its basic simple design and used in those embedded systems where low power consumption and simplicity are more important parameters than speed.

**Carry Look Ahead Adder (CLA)**

Carry Look Ahead Adder is another kind of binary adder which is used in addition of more than 2-bit two operands.

In comparison of RCA, it is faster but design is way more complex than that of RCA. The delay due to sequential carry propagation in RCA, is resolved in CLA by using a special combinational logic circuit. This Combinational circuit generates the carry of each stage in single machine cycle. The carry of each stage generated in advance. The key concept of CLA is its different combinational logic circuit and partial full adder addition. The intermediate combinational circuit generates 2 signals i.e. G (generated carry bits) P (Propagated carry bits). The G signal is a bit position which generates carry if both corresponding bits of operands are logic high '1', in Boolean logic expressed as  $G_i = A_i \otimes B_i$ . 2.1.2 The P signal is a bit position which generates carry if any of the corresponding bits if operands is logic high '1', in Boolean logic expressed as  $P_i = A_i + B_i$ . 2.1.3 The Carry Look ahead logic generates the Carry signal of ith bit in previous stage, with combinational logic of Boolean logic expressed as  $C_{i+1} = G_i + P_i \otimes C_i$ . 2.1.3 This combinational logic helps in generating carry parallelly reducing the delay of carry generation. The Corresponding Sum bits are generated with help of the xorring of corresponding bits of operands.  $S_i = P_i \oplus A_i \oplus B_i$

2.1.4 The output of all bits sums and final carry is generated in 4 machine cycles but, the only problem in CLA concept is the combinational logic for parallel carry generation requires an 'and gate' and 'or gate' of  $n+1$  inputs for  $n$ -bits width of CLA. i.e. for a 4-bit CLA in combinational logic stage it requires an 'and gate' of 5 inputs. By this the fan in and fan out delay by which indirectly we get propagational delays. Although this delay is smaller than RCA but the design complexity, costly design, power consumption causes its limitations for some other kinds of specific application. Time delay calculation for CLA, here we have 3 different parts, i.e. G and P signal generation, Sum generation and Carry Calculation delay. For G and P, we can express delay by following equation  $t_{G,P} = \max(t_{AND}, t_{OR})$ . 2.1.5 The sum calculation delay involves only xor gate delay hence we can express as  $t_S = t_{XOR}$ . 2.1.6 The Carry calculation involves multiple levels of AND & OR gates. For an  $n$ -bit CLA, the carry-out of the last bit involves a maximum of  $\log_2(n)$  levels of gates. By which we can express carry delay by the following equation  $t_C = \log_2(n) * (t_{OR} + t_{AND})$ .

1.7 By all above 3 three equations the final delay for CLA n bit will be given by following equation  $t_{CLA} = t_{XOR} + \log_2(n) * (t_{OR} + t_{AND}) + \max(t_{AND}, t_{OR})$ . 1.8 For example, in an 8-bit CLA all logic gates XOR, AND & OR having unit time delay, from the equation 2.1.8 we can say that 8-unit time delay. I have implemented 8-bit CLA during the internship also, implemented 4-bit design but showing results for 8-bit CLA only. This implementation is similar kind as RCA. And design is extensible to 16-bits or any  $n$ -bit as designed with generate function. 1.3 8-Bit CLA RTL From Xilinx Design Implementation Fig 2.1.4 8-Bit CLA Simulation Output From Xilinx Design Implementation Carry Save Adder (CSA) A CSA is a type of binary digital adder used primarily in computer arithmetic operations. It is designed to add multiple operands simultaneously, which is particularly used in multiplication and accumulation operations. The CSA significantly speeds up the process by not propagating carry bits immediately but rather saving them for later addition. For an  $n$ -bits width CSA, the structure primarily consists of multiple stages of addition, where each stage handles the addition of three inputs and generates two outputs a sum of  $n$ -bits width and a carry bit. The key component of the CSA is basically a full adder. For an  $n$ -bit CSA, in stage 1 of initial addition  $n$  Full Adders, each taking three input bits and generating  $n$  sum bits and  $n$  carry bits.

In stage 2 of addition of sum and carry bits sum bits from the first stage are passed to the next stage and carry bits are shifted left and then added. This stage of shifting and adding continues until we have  $n$ -bits output and a single bit carry output. Timing calculations for CSA, According to structure we have initially a full adder delay. Each full adder delay associated with generating sum and carry bit where, delay of full adder expressed by following equation  $t_{FA} = t_{XOR} + t_{AND} + t_{OR}$ . 1.5 The next delay is of CSA logic delay. The critical path delay is determined by the longest chain of carry propagation. For an  $n$ -bit CSA, the carry is not propagated immediately hence, the delay depends on the depth of carry-save stages. Now each stage involves full adder delays, typically uses  $\log_2(n)$  stages for adding  $n$  bits. The final delay for adding  $n$ -bit three operands, the delay determined by the depth of stages and delay of a single full adder. The final delay expressed as following equation,  $t_{CSA} = k * t_{FA}$ . 1.6 where  $k$  is the number of stages. For example, by considering  $t_{FA} = 4$ -unit delay which consists 2-unit delay for XOR gate, 1 unit delay each for 'AND' and 'OR' gates. For an 8-bit CSA no.

of stages in CSA is 3 from earlier discussion and final delay will of 12-unit time only.Hence, we can conclude that The CSA is an efficient adder for handling multiple inputs simultaneously without the immediate carry propagation delay.I have implemented 8-bit CSA design on Xilinx here are the results of following design implementations in figures.13925550 Fig 2.1.5 8-Bit CLA RTL From Xilinx Design Implementation 190611642 Fig 2.1.6 8-Bit CSA Simulation Output From Xilinx Design Implementation Comparison of Adders Table 2.1 Comparison of adders.Parameter RCA CLA CSA Basic Operation Sequential carry propagation Parallel carry computation Saves intermediate carries for later addition Sum Calculation Sequential Parallel Parallel with multiple stages Carry Calculation Sequential Parallel using generates and propagate signal Saved for later stages Gate count Low High Moderate to High Area Small Large Moderate Power Consumption Low High Moderate Speed Slow Fast In multi-operand addition Complexity Low High Moderate Scalability Poor Good Good Example 8-bit delay 16units 9 units MULTIPLIER DESIGNS Multipliers are fundamental components in digital electronics, used to perform arithmetic multiplication of binary numbers.They are essential in various applications such as digital signal processing (DSP), computer graphics, and general-purpose computing.

The general types of multipliers used in digital electronics are Array Multipliers, Carry Save Array Multipliers, Wallace Tree Multipliers, Sequential Multipliers, Booth Multipliers, Pipelined Multipliers, Bit-Serial Multipliers.Among these Array Multipliers are most basic multipliers and used in understanding of Multipliers Functions.The multipliers used and applied in different application on basis of their speed, efficiency, versatility, accuracy, integration etc.The general applications of multipliers are Digital Signal Processing, Computer graphics, Cryptography, Machine Learning, Embedded systems, etc.Array Multipliers Array Multipliers also known as Fast Multipliers are straight-forward and efficient method for performing binary multiplication.They use an array of adders to sum partial products generated by multiplying each bit of one operand by each bit of the other operand.Let's understand designatiningof2-bit, 3-bit and 4-bit array multipliers and understand difficulties in n-bit multiplier designs.In array multiplier the first stage to get partial products hence for a 2-bit array multiplier let's have 2 operands X and Y of 2 bits which generate the product of 4 bits.Table 2.2 2-bit Multiplication X1 X0 &lt;= Multiplicand operand  $\times$  Y1 Y0 &lt;= Multiplier operand X1Y0

X0 Y0 &lt;= Partial products with Y0 C1X1Y1 X0 Y1  $\times$  &lt;= Partial products with Y1 and weigh added by 21 C2 X1Y1 + C1 X1Y0 + X0 Y1X0 Y0 &lt;= Addition Results P3 P2 P1 P0 &lt;= Product bits In above calculation we can see that X is multiplicand and Y is multiplier.And we get product of 4-bits.There are 4 partial products in above multiplication by multiplying the bits Y0 and Y1 bitwise to X vector and we required 4 'and gates' for the partial product generation.Further in next stage the addition of each partial products with the corresponding weights is done and we get respective product bits generated.In this 2-bit array multiplier we have 2 half adders for addition as we have addition for P1 bit partial products which generates the Carry C1, carried to the next stage and there another half adder adds the next partial product and generated carry considered as 4th bit P3, of the product bits.743123539750 Fig 2.2.1 2-Bit Multiplier RTL From Xilinx Design Implementation 743123285986 Fig 2.2.2 2-Bit Multiplier Simulation Output From Xilinx Design Implementation Now in 3-bit fast multiplier let's see the design and the architecture.Similarly considering two 3 bits operands X and Y where X is multiplicand and Y is multiplier, and we have P vector of 6 bits.

3 3-bit Multiplication X2 X1 X0 &lt;= Multiplicand operand  $\times$  Y2 Y1 Y0 &lt;= Multiplier operand X2Y0 X1Y0 X0 Y0 &lt;= Partial products with Y0 X2Y1 X1Y1 X0 Y1  $\times$  &lt;= Partial products with Y1 and weigh added by 21 X2Y2 X1Y2 X0 Y2  $\times$  &lt;= Partial products with Y2 and weigh added by 22 C23 X2Y2 + C22 X2Y1 + C21 + C12 + X1Y2 X1Y1 + C11 + X1Y1 + X0 Y2 X1Y0 + X0 Y1 X0 Y0 &lt;= Addition Results and carry results where C1x shows the carry generated by addition at first stage and then C2x shows the carry generated by second stage of addition P5 P4 P3 P2 P1 P0 &lt;= Product bits In above calculation no.of adders may not be easy to find but no.of 'and gates' are clearly visible which is 9.For P0 we don't require adder hence P0 is directly fetched.Now for P1 bit we must use a half adder as no carry in from previous stage.The Sum output of that half adder will be P1 and Carry will be carried forward as C11.Now in next stage partial products and carry generated, added using full adders.And by reference to my circuit analysis during work I concluded that it requires 3

half adders and 3 full adders in structure.10687051810385  
Fig 2.2.3 3-Bit Multiplier RTL From Xilinx Design  
Implementation 659130276225 Fig 2.2.4 3-Bit Multiplier  
Simulation Output From Xilinx Design Implementation Now  
let's see about 4-bit array multiplier.Similarly considering  
the A and B vector of 4 bits and output of 8 bits.  
430530678180 Fig 2.2.5 4-Bit Multiplier Multiplication  
Method From reference to above figure, we can say that we  
require 16 'and gates' to get partial products.And with  
reference to my lab-work I concluded that it requires 4 half  
adders and 8 full adders.By which we can conclude for an  
n-bit multipliers no of required components given by  
following equations No.of 'and gates' =  $n^2$  2.2.1 No. of half  
adders =  $n$  2.2.2 No. of full adders =  $n(n-2)$  2.2.3 where n is  
width of input of operands of multipliers.Now considering  
time delays taken by each multiplier and look at any kind of  
disadvantage.For a 2-bit, 3-bit, 4-bit or n-bit multiplier  
design we require only 1 gate delay for partial products.

Now for 2-bit multiplier we have 2 half adders and the 2nd  
half adder is dependent on 1st adder for carry.Let's  
consider 2-unit delay required to propagate carry from 1st  
half adder hence total delay will be of 5-unit (i.e. 1+2+2).  
Now in case of 3-bit multiplier in addition we have 3 levels  
1st for half adder with 1-unit delay,2nd level of full adders  
for intermediate stage with 2-unit delay.And similar at final  
stage 3rd level of 2-unit delay.The total delay about of  
6-unit time.Similarly in case if 4-bit multiplier we have final  
level of adders in 4th stage hence the total time delay can  
be of 8-unit times.The design constraint of this fast  
multipliers or array multipliers is no.of logic and gates and  
full adder blocks required to get a design for n-bit width.  
Such as for a 8-bit array multiplier we need 64 'and gates'  
and about 8 half adders and 48 full adders for simplicity if  
we use all full adders implementation then also we require  
56 different full adders as design of such array multiplier in  
VHDL is not easy because we can't use generate logic for  
addition stage.Also, the chip size and power consumption  
increase with increase in width of multiplier input.

Now let's see the design implementation of 4-bit multiplier  
on Xilinx.8115300 Fig 2.2.6 4-Bit Multiplier RTL From Xilinx  
Design Implementation 697230350520 Fig 2.2.7 4-Bit  
Multiplier Simulation Output From Xilinx Design  
Implementation Booth Multipliers Booth multiplier is kind of  
multiplier works on basis of booth's algorithm of  
multiplication that multiplies two signed binary numbers in  
2's complement notation.Booth uses desk calculators that  
were faster at shifting than adding and created the  
algorithm to increase the speed and performance of the  
multiplier.This multiplier is used more due to its ease in  
scaling and faster multiplication.Also, the design is not that  
complex as compare to fast multipliers.4083051603375 Fig  
2.2.8 Booth's Algorithm Flow Chart Here A is the input  
operand Multiplicand, B is the multiplier operand.Q register  
is initially same as B, Q0 holds the LSB of the Q register.Q-1  
is a 1 bit variable or register.ACC is Accumulator register for  
holding result of intermediate addition and subtraction.

Count holds the maximum width of multiplicand or  
multiplier.The disadvantages of booth logic are high power  
consumption and larger chip area occupation.Even though  
these disadvantages we use Booth Multiplier in few  
applications such as Arithmetic units, DSP, Scientific  
computing and machine learning and neural networks.  
15417801066800 Fig 2.2.9 8-Bit Booth Multiplier RTL From  
Xilinx Design Implementation 7389810 Fig 2.2.10 8-Bit  
Booth Multiplier Simulation Output From Xilinx Design  
Implementation Multipliers Comparison Table 2.4  
Comparison of Multipliers Parameter Booth Multiplier Array  
Multiplier Algorithm Booth's Algorithm Partial product  
additionBasic Operation Encoding and reducing number of  
additions Summing partial products Handling signed  
numbers Efficiently handles signed numbers Requires  
separate handling of sign Number of operations Reduces  
operations for sequences of 1's Number of operations  
proportional to  $n^2$  Speed Faster for large no. of consecutive  
1's Slower for large bit-widths Hardware Complexity More  
complex Simple straight forward Scalability More scalable  
Less scalable Power consumption Lower Higher Efficiency  
More in certain patterns Uniform performance  
Implementation More complex logic control Simple  
repetitive Best use case Signed multiplication large  
bit-widths Smaller bit-widths, simpler applications CHAPTER  
3: VLSI PHYSICAL DESIGN FLOW INTRODUCTION After  
design implementation on Xilinx and having RTL of  
combinational logic circuits, we require a physical chip or IC

fabricated and packaged to use it in day-to-day life. As discussed earlier in introduction chapter that SoC are designed and fabricated to use in mobile phones. That IC is first having architectural design in three domains of VLSI design flow, physical, behavioral, structural domains. Then the fabrication of IC is done. We till now done design implementation in behavioral domain and structural domain to check whether our thoughts or idea can give the similar output as our requirement. Now we will explore about physical domain. The Geometrical design or Layout design is done in physical domain. This process done in sophisticated software tools called as Electronics Design Automation (EDA) or CAD tools. The software EDA tool we used for physical layout is OpenROAD. Now let us explore more about OpenROAD tool next section.

**INTRODUCTION TO OpenROAD EDA TOOL**

The OpenROAD EDA tool is Linux based open source tool which is used to generate RTL-GDSII layout of Verilog language designed entities or modules. If we talk about OpenROAD tool then it consists of various tool chain for different steps of the RTL-GDSII flow layout planning. This chain of tools is called as OpenROAD-flow-scripts (ORFS). The ORFS consists of Magic, Yosys, OpenSTA, iverilog, gtkwave, klayout, OpenLane, OpenROAD. Each tool has its own use in different stages of RTL-GDSII flow.

Likewise Magic and Klayout are for layout planning. Yosys used as logic synthesis tool which synthesizes the raw verilog file to required SDC file for next steps of routing, netlisting and floorplanning of ICs. Earlier stages there was no tool for clock tree synthesis but now we have tools like OpenSTA or OpenCLOCK for static timing analysis and clock tree synthesis. iverilog tool used to have HDL simulations inside the ORFS. gtkwave is waveform viewer. And at last, the main OpenROAD or OpenLane where we call all this tools by its GUI and command prompt window in GUI. Let us see how we can install and use all those tools to design IC from RTL to GDSII. Step-by-step Installation Process. The basic required system for using ORFS is Ubuntu Linux Based System. For latest Ubuntu 24.04 LTS we require at least 8 GB RAM recommended along with 100 GB of free space HDD or SSD and a quad processor with 2.4 GHz clock or better than that. A stable internet connectivity is also recommended probably ethernet or Wi-Fi as software installation becomes bad to worst if internet is not working properly and may stuck in

between any step of installation process. A dual boot laptop or desktop, or an ubuntu based system is required, do not try, or waste your time trying any other methods of Linux installation in your system such as WSL or VMBox. Simply install ubuntu linux in your system and do the step to install ORFS. To install Ubuntu 24.04 by your own efforts you should have to create bootable pen-drive of 16 GB, and Then by entering to BIOS setup doing some changes you will be able to do boot in Ubuntu and Windows on single system. After installation of Ubuntu do 2 to 3 times of check of booting and try to install ORFS after 4 to 5 hours of installation of Ubuntu in system, if you using your old Ubuntu system then you can go through the installation steps given below. Installation steps for ORFS are as follows:

- Open the command terminal upgrade, and update the packages and whole ubuntu for new releases may required in further steps by using command `sudo apt-get update`, `sudo apt upgrade` (reboot recommended after packages upgradation)
- Install the git package which will be used to clone GitHub repositories to your system by using the command, `sudo apt install git -assume-yes`
- Install the dependencies and build essential by prompting command, `sudo apt install -y build-essential`
- Install the Python using following command, `sudo apt install -y python3-venv`

Next step is to make the default 'sh' to be 'bash' rather than 'dash' you can do it by following command, `sudo rm /bin/sh && sudo ln -s /bin/bash /bin/sh`. After that you should create directory or work area in ubuntu for ORFS by using following command, `mkdir -p Work/vlsi/tools`. Now we will move to tools directory and install Yosys and OpenROAD in that directory. The command should be followed as given, `cd ~/Work/vlsi/tools`, `git clone -recursive https://github.com/The-OpenROAD-Project/OpenROAD-flow-scripts`. Setup of OpenROAD and Yosys by following command, `mkdir Open-ROAD-flow-scripts`, `cd ~Work/vlsi/tools/OpenROAD-flow-scripts`, `sudo ./setup.sh`. Installation of OpenROAD and Yosys by following command, `./build_openroad.sh -local` (this step will take about 30-40 minutes to install without any error).

Installation of dependencies of Magic VLSI tool by using following commands,

- `cd && sudo apt-get update`
- `&& sudo apt-get install m4 -assume-yes`
- `&& sudo apt-get install tcsh --assume-yes`
- `&& sudo apt-get install csh --assume-yes`
- `&& sudo apt-get install libx11-dev --assume-yes`
- `&& sudo apt-get install tcl-dev tk-dev --assume-yes`
- `&& sudo apt-get install libcairo2-dev --assume-yes`
- `&& sudo apt-get install mesa-common-dev libglu1-mesa-dev --assume-yes`

```

& sudo apt-get install libncurses-dev
--assume-yes Installing Magic VLSI tool by using following
command as given below.git clone https://github.
com/RTimothyEdwards/magic.git & sudo mkdir yosys
& cd yosys & sudo make
& sudo make install (this process of installation
may take 30-45 minutes depending on stability and
connectivity of internet you are providing.Installation of the
iverilog tool for HDL simulations in ORFS,sudo apt-get install
-y iverilog--assume -yes Installation of the gtkwave
waveform simulation tool in ORFS,sudo apt install gtkwave
--assume-yes Installation of the Klayout, layout planning toll
in ORFS,sudo apt install klayout --assume -yesInstallation of
docker in ubuntu to install the OpenLane by docker
method, sudo apt-get removedocker docker-engine docker.
io containerd runc --assume-yes sudo apt-get update
--assume-yes sudo apt-get install
apt-transport-https ca-certificates curl gnupg lsb-release
--assume-yes curl-fsSL https://download.docker.
com/linux/ubuntu/gpg | sudo gpg --dearmor
-o /usr/share/keyrings/docker-archive-keyring.gpg
--yes echo "deb [arch=amd6
signed-by=/usr/share/keyrings/docker-archive-keyring.

gpg] https://download.com/linux/ubuntu/$(lsb_release -cs)
stable" | sudo tee /etc/apt/sources.list.d/docker.list
&gt;/ddev/null sudo apt-get update --assume-yes
apt-get install docker-ce-cli containerd.io --assume-yes
Installation of OpenLane tool under the ORFS tool chain,
cd git clone https://github.
com/The-OpenROAD-Project/OpenLane.git mkdir
OpenLane cd OpenLane sudo makesudo make install By
following above steps, we can install all the required tools
for the ORFS tool chain, now we can proceed to the step to
install the open source PDK supported by OpenROAD which
will provide design constraints and standard cell library for
our design implementation.By default, with OpenLane and
ORFS we get skywater130 PDK and nangate45 PDK support,
for other PDKs such as GF180MCU, SKY90FD,
GlobalFoundries are such PDKs.The installation of the PDK
in the system is not that tough you can go through website
link given below to install PDKs the link for installation
process is: http://www.opencircuitdesign.
com/open_pdk/install.html After installation of all the tools
we need to verify either all the tools are successfully
installed or not.

```

These current steps support verilog language synthesis
only.For implementing and synthesis of VHDL modules in
yosys gnat and ghdl, so that we can use VHDL files and
parse for synthesis.Installation Verification Process.To verify
the installation of ORFS tools the best is to use them
directly or simply enter each command one by one by which
information of the this ORFS tools or version may be visible
to you in terminal or if the version information is not
visible then you must reinstall the respective tool by
following respective step mentioned above again.The
command to verify each tool installation given in following
table.Table 3.1 Command table for verification Command
Command Output yosys -V Version of yosys installed will be
displayed openroad -version Version of openroad will be
visible gtkwave -v gtkwave installed version will be displayed
iverilog -V iverilog installed version will be displayed docker
--version docker version will be displayed opensta either
GUI or opensta or information will be displayed klayout -v
klayout version will be displayed magic --version

magic tool installed version will be displayed ./flow.tcl -help
(this command should be used by moving to OpenLane
directory and then run this command) This will display the
information of OpenLane flowscript.ls \$PDK\_ROOT/sky130A
or ls \$PDK\_ROOT/pdk\_name This will list the content of PDK
directory.RTL TO GDSII FLOW The ORFS has different tools
by which we can go through RTL to GDSII flow easily if we
provide proper parameters and PDK files.Later, we will
discuss about how we can get RTL to GDSII step by step.
Now let us understand about what is RTL to GDSII flow.The
ORFS is autonomous software but we will use it in manual
order step by step to debug in between any error.Now see
the flow of RTL to GDSII in following figure.9786511616710
Fig 3.3.1.a RTL to GDSII Design Flow As per the last figure
we need to create verilog file, and then from PDK we must
select any PDK and then use that PDK's library file and
design constraint file during the synthesis process through
the yosys.1906846666 Fig 3.3.1.b RTL To GDSII Flow Using
ORFS Now let us understand about each part of Physical
design flow given in figure 3.

3.1.b Synthesis: The process of synthesis is to synthesize the netlist file of the module using selected standard cell library provided by the vendor. The input of the synthesizer used yosys in the ORFS are verilog file and standard cell library which gives output of Gate level netlist and SDC of the designed module. Floorplan: The Floorplan will initiate the basic area of die and core which will be used to design on actual silicon substrate. It helps in random IO placement which further rectified according to design and tapcell insertion for the design. Placement: The placement in RTL to GDSII consists of many parts such as Globalcell placement, IO placement, Global Placement with placed Ios, Resizing and buffer settings and detailed placement, provides various parameters and organizes the different objects such as IO pins, Buffers placement and give proper distribution. Clock Tree Synthesis: This is done with help of opensta tool, which is used whenever we have any kind of clock driven part inside the chip and it will help in dividing the clock and proper clock functioning. Routing: This part helps in interconnections between vias and metals layers of the different layers and interconnections between different blocks of design inside the chip. Finishing: In general, wherever we use checkpoint, report and repair we are checking for any kind of faults and error in design which is termed as Finishing of design. Now let us see the step-by-step process of getting RTL to GDSII final layout from a verilog file. Design realization and implementation by using PDK of vendor nangate45 which support 45nm technology window design, and consist

design constraints and standard cell library for design implementation. The PDK will be provided by the vendor from whom you wished to fabricate your IC, here we using open-source PDK for our designs Note:- Commands and outputs are in Italics and Bold. Also due to irregularity in sentence width the justify alignment isn't used during the steps as it seems too bad format, as of example you can see the above paragraph ending. To create a verilog file you can use by default text editor and save it in any folder in home directory or if you installed by following our method then you can do it by saving it in tools folder's any new folder, alongwith .v extension. Open terminal and write command: yosys . To access the yosys for synthesis. Open your verilog file by using command: read\_verilog  
\$/file\_path/file\_name.v read\_verilog  
/home/darshit-mehta/run01/CarryLookAheadAdder\_8bit.v In this step we will get output message on terminal as Generating RTLIL representation for module 'CarryLookAheadAdder\_8bit'. Successfully finished Verilog frontend. Checking, expanding, and cleaning of the design hierarchy, which will be done by

following command: hierarchy -check -top CarryLookAheadAdder\_8bit By performing this step you will get the output such that analyzing design hierarchy. Top module: \CarryLookAheadAdder\_8bit Removed unused 0 modules Note:- The setup we got limitation of setting only one entity module, if your verilog code has more than one entity module then you may get error at previous step or any of the next step. Hence to ensure the least error chances implement your design based in basic gates rather than using more than one entity. Conversion "processes" into multiplexers and registers (the internal representation of behavioral verilog code) by using command: proc . After this you should wait until any error message shows or proceed to next step if no error message shows. Perform some basic optimizations and cleanups by using following command: opt This will show message at last that Finished OPT passes. (There is nothing left to do.) After getting this message you can proceed to next step. Analyze and optimize finite state machine for your design by using following command: fsm By following this step you get last message as Executing FSM\_MAP pass (mapping FSMs to basic logic). After this repeat Step 6. Note: From this onward after every step, it is good practice to use command: opt for performing basic optimization and cleanups. Analyze memories and create circuits to implement them for your design by using following

command: memory This kind of message will be shown in ending if this process Executing MEMORY\_MAP pass (converting memories to logic and flip-flops). Map coarse-grain RTL cells (adders, etc.) to fine-grain logic gates (AND, OR, NOT, ETC...) by using following command: techmap Successfully finished Verilog frontend. This message may be displayed or if you get any error you can restart process or debug it if error is understandable. Map registers to available hardware flip-flop from lib by using following command: dfllibmap -liberty /home/darshit-mehta/Work/vlsi/tools/OpenROAD-flow-scripts/tools/OpenROAD/test/Nangate45/Nangate45\_typ.lib \$/home/darshit-mehta/Work/vlsi/tools/OpenROAD-flow-scripts/tools/OpenROAD/test/Nangate45 this is the file path of standard cell library provided by vendor. Wait till the process end and proceed to next step. Map logic to available hardware gates by using the command: abc -liberty /home/darshit-mehta/Work/vlsi/tools/OpenROAD-flow-scripts/tools/OpenROAD/test/Nangate45/Nangate45\_typ.lib By performing this step you will get message displaying some useful information. Re-integrating ABC results. ABC RESULTS: NAND2\_X1 cells: 3 ABC RESULTS: AOI21\_X1 cells: 3 ABC RESULTS: AND2\_X1 cells:

4 ABC RESULTS: OR2\_X1 cells: 4 ABC RESULTS: AOI221\_X1 cells: 1 ABC RESULTS: NOR2\_X1 cells: 5 ABC RESULTS: XOR2\_X1 cells: 4 ABC RESULTS: OAI21\_X1 cells: 4 ABC RESULTS: XNOR2\_X1 cells: 12 ABC RESULTS: internal signals: 115 ABC RESULTS: input signals: 17 ABC RESULTS: output signals: 9 Removing temp directory. Next step is to flattening of design using command: flatten Executing FLATTEN pass. (flatten design) (This message may be seen) Replacement of undef values with defined constants this is important as if we don't do this then our design may get any error in any next step. The command for this task is : setundef -zero Removal of unused cells and wires is also important to optimize our design. The command for this task is: clean -purge Next step is technological mapping of i/o pads (or buffers) by using the command:iopadmap -outpad BUF\_X2 A:Z -bits Use command : clean .To remove unused cells and wires.To do some important calculations such as die area or core area of IC we require some stats this statistics data obtain by using command: stat -liberty /home/Darshit-mehta/Work/vlsi/tools/OpenROAD-flow-scripts/tools/OpenROAD/test/Nangate45/Nangate45\_typ.lib Here "/home/darshit-mehta/Work/vlsi/tools/OpenROAD-flow-scripts/tools/OpenROAD/test/Nangate45/Nangate45\_typ.lib" is path of the standard cell library file, which will give stats related such as no.

components, wires, cells, processes and at last the chip area value in micrometers<sup>2</sup> units. This will determine the chip core area and die area in substrate during fabrication process. Printing statistics.==> CarryLookAheadAdder\_8bit ==> Number of wires: 38 Number of wire bits: 66 Number of public wires: 5 Number of public wire bits: 26 Number of memories: 0 Number of memory bits: 0 Number of processes: 0 Number of cells: 49 AND2\_X1 4 AOI21\_X1 3 AOI221\_X1 1 BUF\_X2 9 NAND2\_X1 3 NOR2\_X1 5 OAI21\_X1 4 OR2\_X1 4 XNOR2\_X1 12 XOR2\_X1 4 Chip area for module "CarryLookAheadAdder\_8bit": 59.052000 This will be displayed message may vary according to your components. Rename the object in the design is the next step , we can assign short auto-generated names to all the selected wires and cells with private name or use this command: rename -enumerate to do same. Overwriting the design to verilog file is also included in this step this is done by using command: write\_verilog -noattr CarryLookAheadAdder\_8bit1\_final.v Now to generate BLIF file or netlist we must use the following command: write\_bif -buf BUF\_X2 A Z CarryLookAheadAdder\_8bit1\_mapped\_withbuf.bif Now we should check the netlist generated and stored in BLIF file by previous step with help of graphviz, it will generate schematic graph of our netlist. This can be done by using command: show -stretchIn this step you will be able to see the netlist as shown in figure.Fig 3.

3.2 RTL to Gate Level Netlist of CarryLookAheadAdder\_8bit  
 Now you have exit the yosys using command: exit , and interact with OpenroadGUIby using command: openroad -gui Note: Until this step we were working over yosys the synthesis tool now we must go for further steps to generate final GDS layout using OpenROAD tool of ORFS.The GUI of OpenROAD is command line-based tool hence at each step has different commands, the commands will be same font as until we see in previous steps.Create a SDC file with text editor and give name as SDC and save in .csv extension. This file also in same directory where you have previously saved verilog file. You may notice some changes that verilog file if you did not save the synthesized verilog file in different name. The content of SDC file is create\_clock [get\_ports clk] -name core\_clock -period 0.4850 set\_all\_input\_output\_delays Now you must save this SDC file and final verilog file in folder with following path, \$/home/darshit-mehta/Work/vlsi/tools/OpenROAD-flow-scripts/tools/OpenROAD/test . After that you may proceed for further steps. Note: The chip area will give you idea about estimation of chip area and die area, You can either you can keep same as chip area or round it to nearest ten for sake of simplicity and for larger areas you have to choose area by trial and error method. Although we have a relation that if  $u = \text{utilization efficiency of chip}$ , then  $\text{die area} = (\text{chip area} * 100) / u$ , where  $u$  ranges between 30% to 90% practically may more different. And according to die area you can set core area. Now we will put following commands in command prompt of openroad GUI.set design "CarryLookAheadAdder\_8bit"set top\_module "CarryLookAheadAdder\_8bit"set synth\_verilog "CarryLookAheadAdder\_8bit1\_final.v" set sdc\_file "CarryLookAheadAdder\_8bit.sdc" #set die\_area {0 0 42 42}set die\_area {0 0 42 42}#set core\_area {2.5 2.5 40 45} set core\_area {2.5 2.5 40 45} After having this command in the command window now you can press enter to set these parameters to the openroad for the design. In this step you have to give command of reading the design files to the openroad by using commands given below.read\_libraries read\_verilog \$synth\_verilog link\_design \$top\_module read\_sdc \$sdc\_file In this step we will have STA network instance count for all other parameters required to generate the final layout, this step will help in creating all other parameters.utl::metric &quot;IPF::ord\_version&quot; [ord::openroad\_git\_describe] # Note that sta::network\_instance\_count is not valid after tapcells are added.utl::metric &quot;IPF::instance\_count&quot; [sta::network\_instance\_count] In this step we will initiate process of floorplanning.

```

initialize_floorplan -site $site \ -die_area $die_area \
-core_area $core_areaBy which you will get floorplan figure.
3.3 Floorplan Command Output Window Now to optimize
the design we must remove unused or unrequired buffers
by using commands, source $tracks_file# remove buffers
inserted by synthesis remove_buffers We will get output at
output console: [INFO]RSZ-0026] Removed 16 buffers. Now
next step is random IO placement by using the following
commands# IO Placement (random) place_pins -random
-hor_layers $io_placer_hor_layer -ver_layers
$io_placer_ver_layer Fig 3.3.4 IO_Placement_Random
Command Output Window Next step is macro-placement
which can be done by using command, # Macro Placement if
{ [have_macros] } {global_placement -density
$global_place_density macro_placement -halo
$macro_place_halo -channel $macro_place_channel} Now
our next target is to create tapcell insertion by using
following command, # Tapcell insertion even tapcell
$tapcell_args This will show some significant changes in
output window, which shown in Fig 3.3.5 Fig 3.3.5 Tapcell
Insertion Command Output Window 145414422 Insertion
of power distribution network using following command, # Power
distribution network insertion source
$pdn_cfgpdngen This command renders some significant
changes to output window, Fig 3.

3.6 PDN Command Output Window The next step is of
global placement of different partslayers interlinks, we can
see some red instances in the chip design area by using
following commands for global placement, # Global
placement foreach layer_adjustment
$global_routing_layer_adjustments { assign
$layer_adjustment layer
adjustment set_global_routing_layer_adjustment $layer
$adjustment} set_routing_layers signal
$global_routing_layers \clock
$global_routing_clock_layers set_macro_extension
2global_placement -routability_driven -density
$global_place_density \pad_left $global_place_pad
-pad_right $global_place_pad Fig 3.3.7 Global Placement
Command Output Window 57361174200 Now we will
organize the Input and Output Placements, by using
following commands, # IO Placement place_pins -hor_layers
$io_placer_hor_layer -ver_layers $io_placer_ver_layer Fig 3.
3.8 IO Placement Command Output Window 102871422
Now we must set a checkpoint by using following
command, # checkpointset global_place_db
[make_result_file ${design}].${platform}.global_place.
db] write_db $global_place_db Now we have to optimize and
repair the design by maximum of slew, capacitance and
fanout violations and normalizing the slew by following
commands, # Repair max slew/cap/fanout violations and
normalize slew source $layer_rc_fileset_wire_rc -signal
-layer $wire_rc_layerset_wire_rc -clock_layer
$wire_rc_layer_clkset_dont_use
$don't_use estimate_parasitics -placement repair_design
-slew_margin $slew_margin -cap_margin
$cap_margin repair_tie_fanout -separation $tie_separation
$tiel0_port repair_tie_fanout -separation $tie_separation
$tiehi_port set_placement_padding -global -left
$detail_place_pad -right
$detail_place_pad detailed_placement# post resize timing
report (ideal clocks) report_worst_slack -min -digits
3 report_worst_slack -max -digits 3 report_tns -digits 3#
Check slew repair report_check_types -max_slew
-max_capacitance -max_fanout -violators utl::metric
&quot;RSZ::repair_design_buffer_count&quot;
[rsz::repair_design_buffer_count] utl::metric
&quot;RSZ::max_slew_slack&quot; [expr
[sta::max_slew_check_slack_limit] * 100] utl::metric
&quot;RSZ::max_fanout_slack&quot; [expr
[sta::max_fanout_check_slack_limit] * 100] utl::metric
&quot;RSZ::max_capacitance_slack&quot;
[expr [sta::max_capacitance_check_slack_limit] * 100] Fig 3.
3.9 Repair Design Command Output Window The console
outputs and analysis we get at console window
are, Placement Analysis-----total
displacement 47.

8 uaverage displacement 0.5 umax displacement 2.3
uoriginal HPWL 420.3 ulegalized HPWL 490.7 udelta HPWL
17 %worst slack 0.202 worst slack -0.042 tns -0.
070-91226-196426 Now next part is also important as we
do CTS in next part, using following command group, # Clock
Tree Synthesis# Clone clock tree inverters next to register
loads# socts does not try to buffer the inverted clocks.
repair_clock_inverters clock_tree_synthesis -root_buf
$cts_buffer -buf_list $cts_buffer \sink_clustering_enable \
-sink_clustering_max_diameter $cts_cluster_diameter# CTS
leaves a long wire from the pad to the clock tree root.
repair_clock_nets# place clock buffers detailed_placement#
checkpointset cts_db [make_result_file
${design}].${platform}.cts_db] write_db $cts_db This will set
buffers and clock buffers and give output of no. of valid
clock nets according to design, The most important
parameter out by this commands is Using max wire length
which is 693 um in our design.

```

Placement Analysis-----total  
 displacement 0.0 uaverage displacement 0.0 umax  
 displacement 0.0 uoriginal HPWL 490.7 ulegalized HPWL  
 490.7 udelta HPWL 0 % Now setup and hold timing repair  
 for the chip designin another part of CTS, by using following  
 commands,# Setup/hold timing repairset\_propagated\_clock  
 [all\_clocks]# Global routingis fast enough for the flow  
 regressions.# It IS NOT FAST ENOUGH FOR PRODUCTION  
 USE.set repair\_timing\_use\_grt\_parasitics 0if {  
 \$repair\_timing\_use\_grt\_parasitics } # Global route for  
 parasitics - no guide filerequiredglobal\_route  
 -congestion\_iterations 100estimate\_parasitics  
 -global\_routing) else {estimate\_parasitics  
 -placement}repair\_timing -skip\_gate\_cloning# Post timing  
 repair.report\_worst\_slack -min -digits 3report\_worst\_slack  
 -max -digits 3report\_tns -digits 3report\_check\_types  
 -max\_slew -max\_capacitance -max\_fanout -violators -digits  
 3util::metric&quot;RSZ::worst\_slack\_min&quot;  
 [sta::worst\_slack -min]utl::metric  
 &quot;RSZ::worst\_slack\_max&quot; [sta::worst\_slack  
 -max]utl::metric &quot;RSZ::tns\_max&quot;  
 [sta::total\_negative\_slack -max]utl::metric  
 &quot;RSZ::hold\_buffer\_count&quot;  
 [rsz::hold\_buffer\_count]Those commands will give rendered  
 output for virtual clock core\_clockcannot be propagated  
 which may differ design by design, and an Placement  
 Analysis as shown  
 in down outputs,Placement  
 Analysis-----total displacement 12.4  
 uaverage displacement 0.1 umax displacement 2.6  
 uoriginal HPWL 495.3 ulegalized HPWL 509.7 udelta HPWL  
 3 % Let us have now detailed placement of our design using  
 following commands,# Detailed  
 Placementdetailed\_placement# Capture utilization before  
 fillers make it 100%utl::metric &quot;DPL:utilization&quot;  
 [format %.1f [expr [rsz::utilization] \* 100]]utl::metric  
 &quot;DPL:design\_area&quot; [sta::format\_area  
 [rsz::design\_area] 0]# checkpointset dpl\_db  
 [make\_result\_file \${design}\_\$(platform)\_dpl.db]write\_db  
 \$dpl\_dbset verilog\_file [make\_result\_file  
 \${design}\_\$(platform).v]write\_verilog \$verilog\_file Fig 3.3.10  
 Detailed Placement Command Window Output The console  
 will give some outputs parameters of designgiven as also  
 enlists the default vias layer by layer vias, After all this  
 renderingwe now do global routing by using following  
 commands,# Global routingpin\_access  
 -bottom\_routing\_layer \$min\_routing\_layer \  
 -top\_routing\_layer\$max\_routing\_layerset route\_guide  
 [make\_result\_file \${design}\_\$(platform).  
 route\_guide]global\_route -guide\_file \$route\_guide \  
 -congestion\_iterations 100set verilog\_file [make\_result\_file  
 \${design}\_\$(platform).  
 v]write\_verilog -remove\_cells \$filler\_cells \$verilog\_fileThis  
 command will give some parameters such as,Reading tech  
 and libsUnits: 2000Numberof layers: 21Number of macros:  
 135Number of vias: 30Number of viarulegen: 19Reading  
 design.Design: CarryLookAheadAdder .8bitDie area: ( 0 0 )(  
 84000 84000 )Number of track patterns: 20Numberof DEF  
 vias: 0Number of components: 94Number of terminals:  
 26Number of snets: 2Number of nets:59 And list of vias  
 different metal vias, This will be also part of globalrouting  
 report Start pin access.Complete 57 pins.Complete 17  
 unique inst patterns.Complete 42 groups.#scanned  
 instances = 94#unique instances = 21#stdCellGenAp =  
 474#stdCellValidPlanarAp = 0#stdCellValidViaAp =  
 335#stdCellPinNoAp = 0#stdCellPinCnt =  
 134#instTermValidViaApCnt = 0#macroGenAp =  
 0#macroValidPlanarAp = 0#macroValidViaAp =  
 0#macroNoAp = 0Complete pin access.Now we will repair  
 any possible defects of Antenna by using following  
 commands,# Antennarepairrepair\_antennas -iterations  
 5check\_antennasutl::metric &quot;GRT::ANT::errors&quot;  
 [ant::antennaViolation\_count]This will be give output of any  
 net and pin violations,and give output asFound 0 net  
 violations.Found 0 pin violations.

Now the next part is filler placement in design by using following commands,

```

# Fillerplacementfiller_placement
$filler_cellscheck_placement -verbose# checkpointset fill_db
[make_result_file ${design}_${platform}_fill.db]write_db
$fill_db There will be significant changes in output window of design, Fig 3.3.11 Filler Placement Command Window
Output Now we will be doing detailed routing of ourdesign using following commands,
```

# Detailed routing# Run pin access again after inserting diodes and moving

```

cellspin_access -bottom_routing_layer $min_routing_layer \
-top_routing_layer $max_routing_layerset_thread_count
[exec getconf _NPROCESSORS_ONLN]detailed_route
-output_drc
[make_result_file&quot;${design}_${platform}_route.drc
rpt&quot;] \output_maze [make_result_file
&quot;${design}_${platform}_maze.log&quot;]
\no_pin_access \save_guide_updates
\bottom_routing_layer $min_routing_layer
\top_routing_layer $max_routing_layer \verbose
Owrite_guides [make_result_file
&quot;${design}_${platform}_output_guide.mod&quot;]set
drv_count [detailed_route_num_drvs]utl::metric
&quot;DRT::drv&quot; $drv_countcheck_antennasutl::metric
&quot;DRT::ANT::errors&quot;
[ant::antennaViolationCount]set routed_db
[make_result_file ${design}_${platform}_route.db]write_db
$routed_dbset routed_def [make_result_file
${design}_${platform}_route.def]write_def $routed_defThis
commands will run at instances to provide different output checks and only someparameters which required internally to display design This will help in extraction of SPEF#
Extractionif $rcx_rules_file != &quot;&quot; } {
define_process_corner-ext_model_index 0 X
extract_parasitics-ext_model_file $rcx_rules_file set spef_file
[make_result_file ${design}_${platform}.spef] write_spef
$spef_file read_spef $spef_file else { # Use global routing
based parasitics inlieu of
rc extraction estimate_parasitics -global_routing} These
commands will check the give some error checks and final
SPEF file for detailed information of interconnections
between different components and gates, pins to thechip
and design.To get thefinal report of the design and final
design we can use the following commands,
```

# Final Report

```

report_checks -path_delay min_max -format
full_clock_expanded \fields {input_pin slew capacitance}
-digits 3report_worst_slack -min -digits 3report_worst_slack
-max -digits 3report_tns -digits 3report_check_types
-max_slew -max_capacitance -max_fanout -violators -digits
3report_clock_skew -digits 3report_power -corner
$power_cornerreport_floating_nets
-verbosereport_design_areaultl::metric
&quot;DRT::worst_slack_min&quot; [sta::worst_slack
-min]utl::metric &quot;DRT::worst_slack_max&quot;
[sta::worst_slack -max]utl::metric &quot;DRT::tns_max&quot;
[sta::total_negative_slack -max]utl::metric
&quot;DRT::clock_skew&quot; [expr
abs([sta::worst_clock_skew -setup])]# slew/cap/fanout
slack/limitutl::metric &quot;DRT::max_slew_slack&quot;
[expr [sta::max_slew_check_slack_limit] * 100]utl::metric
&quot;DRT::max_fanout_slack&quot; [expr
[sta::max_fanout_check_slack_limit] * 100]utl::metric
&quot;DRT::max_capacitance_slack&quot; [expr
[sta::max_capacitance_check_slack_limit] *100];# report
clock period as a metric for updating limitsutl::metric
&quot;DRT::clock_period&quot; [get_property [index
[all_clocks] 0]period]# not really useful without pad
locations#set_pdnsim_net_voltage -net $vdd_net_name
-voltage $vdd_voltage#analyze_power_grid -net
$vdd_net_name The final report can be found in results
folder of test for all detailed information and parameters if
the designed chip, This is the final GDSII layout given in
figure below, Fig3.
```

3.12 The Final CarryLookAheadAdder\_8bit Design  
Output 2046804377055 SOME DESIGN IMPLEMENTS I have  
designed some designs implemented on basis of the PDK  
nangate45 which uses 45nm technology.

#### 4.1 Shift\_Register

Final GDSII Layout Design The CSA design implemented  
using nangate45 standard cell library, with set die\_area {0 0  
60 60}, set core\_area {5 2 56 60}, max wire length of 693  
um.4.2 mux\_8bits Final GDSII Layout Design The RCA  
design implemented using nangate45 standard cell library,  
with set die\_area {0 0 40 40}, set core\_area {4 2 36 37}, max  
wire length of 693 um.4.3 demux\_8bits Final GDSII Layout  
Design The 8-bit Multiplier design implemented using  
nangate45 standard cell library, with set die\_area 0 0 50 55},  
set core\_area {4 3 45 50}, maxwire length of 693 um.  
CHAPTER 4: SUMMARY Let me summarize the activities I  
done during my internship.Initially I was doing design  
implementations on Xilinx and trying to install ORFS.I had  
learned about the different kind of advanced adders used in  
computer architecturealso, learned about the multipliers  
which applied as DSP, and convolutors for Machine  
Learning and Deep Learning Model architectures.I had  
explored about the lab facilities available to students and  
researchers in the SVNIT.The installation ORFS was not  
easy, I have spent over a week to just get that ORFS on my  
system.And after getting the software ORFS I explored  
about how to use it, I got familiar to code hub which is  
known as github.Before all this I learned how to use ubuntu  
basics as that software is a opensource hence not available  
in Windows based system.

The ORFS supports many other PDKs also which make its more useful for initial research and design implementations. References/ Bibliography As per the guidelines and the references given by GTU, Ahmedabad. I have tried to keep this thesis report / Internship Report as sole creator and writer me, although 100% not be done by me hence I have taken references of designs and some terms and important images and parts from the web, knowingly or somethers may show in plagiarism report, Some of references used by me knowingly are listed below, Invent Logics-ShopNow for Xilinx FPGA development boards (allaboutfpga.com) The OpenROAD Project · GitHub Online Collaborative Whiteboard | Sketchboard VLSI Physical Design with Timing Analysis - Course (nptel.ac.in) OpenROAD Flow Scripts Tutorial — OpenROAD Flow documentation (openroad-flow-scripts.readthedocs.io) OpenLane using Codespaces : RTL-to-GDSII flow. - Part-2 (youtube.com) https://www.youtube.com/watch?v=\_AXknRBk4QI OpenROAD and efabless OpenLane at the CHIPKIT tutorial, ISCA-2020 (youtube.com) And there may be some other similar references can be listed in Plagiarism report which are unknowingly references.

### Matched Sources

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# GUJARAT TECHNOLOGICAL UNIVERSITY

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B.E. SEMESTER VII, ACADEMIC YEAR 2024-2025

Date of certificate generation : 20 September 2024 (19:39:46)

This is to certify that, *Sahu Arabinda Kailash* ( Enrolment Number - 210230111008 ) working on project entitled with *VLSI Physical Design* from *Electronics & Communication Engineering* department of *DR. S & S.S. GHANDHY GOVERNMENT ENGINEERING COLLEGE, SURAT* had submitted following details at online project portal.

Internship Project Report	Completed
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Name of Student : Sahu Arabinda Kailash

Name of Guide : Mrs.Pithadia Parul Vasantlal

Signature of Student :

A handwritten signature in blue ink, appearing to read "Arabinda Kailash".

\*Signature of Guide :

A handwritten signature in blue ink, appearing to read "Pithadia Parul Vasantlal".

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